

# ECE 105: Introduction to Electrical Engineering

Lecture 1

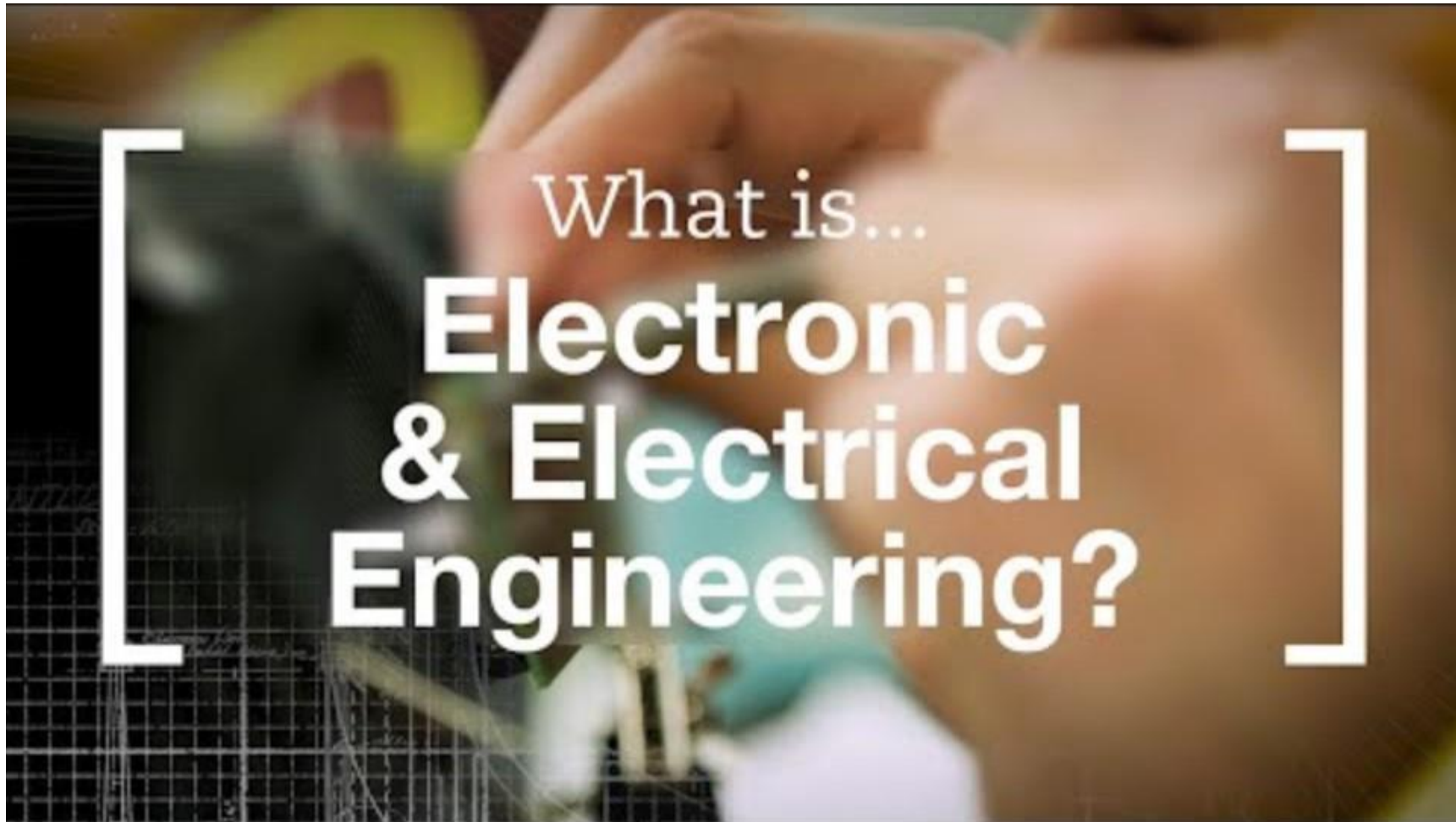
Introduction to EE, and ECE 105

Yasser Khan

Rehan Kapadia

# What is Electrical Engineering?

- Electrical Engineering is an engineering discipline concerned with the study, design, and application of equipment, devices, and systems which use electricity, electronics, and electromagnetism.



# Let's look at EE at play: 3 little pigs demo by Neuralink



# Neuralink – the neural implant

## LINK V0.9

1024 channels per Link

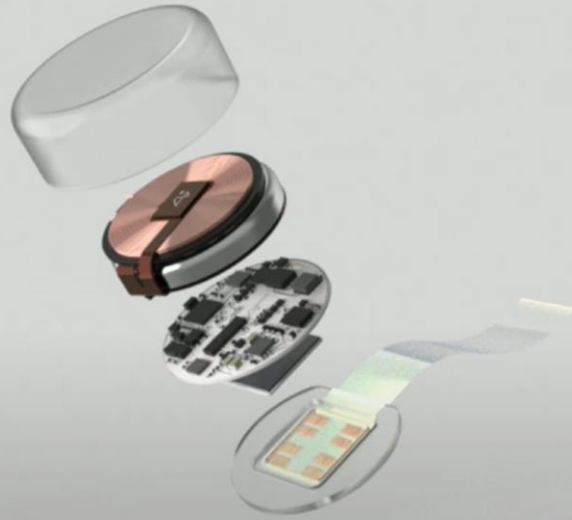
23 mm x 8 mm

Flush with skull (invisible)

6-axis IMU, temperature, pressure, etc.

Megabit wireless data rate, post compression

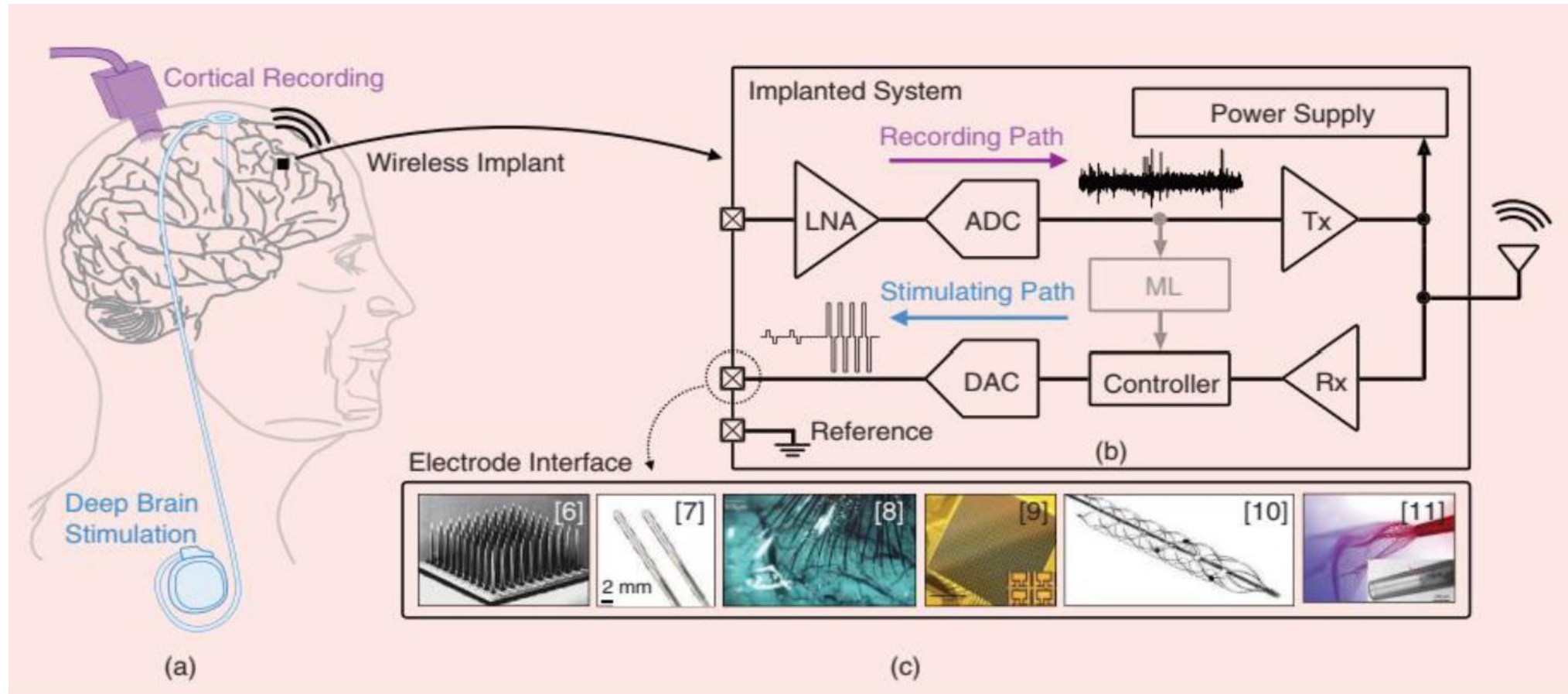
All day battery life



- Every step of the neural implant design and fabrication requires electrical engineering

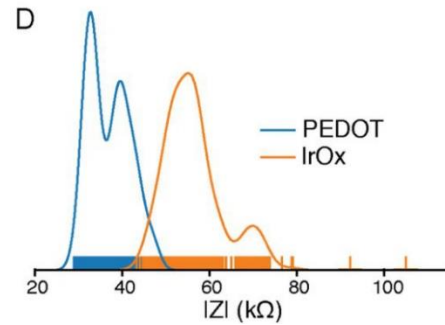
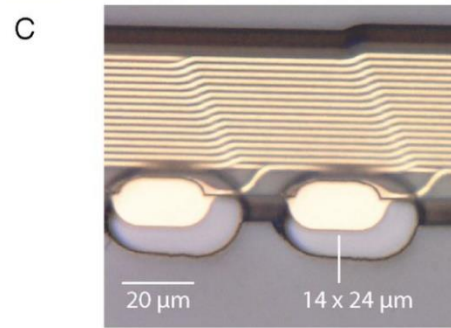
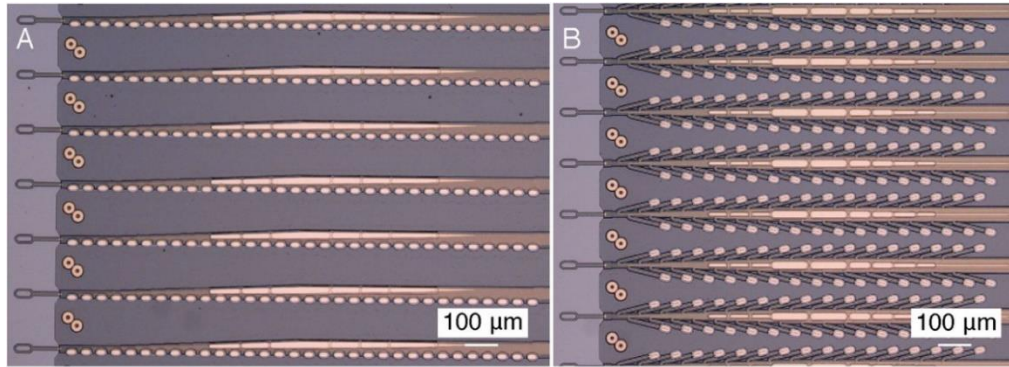


# Neural interfaces – under the hood

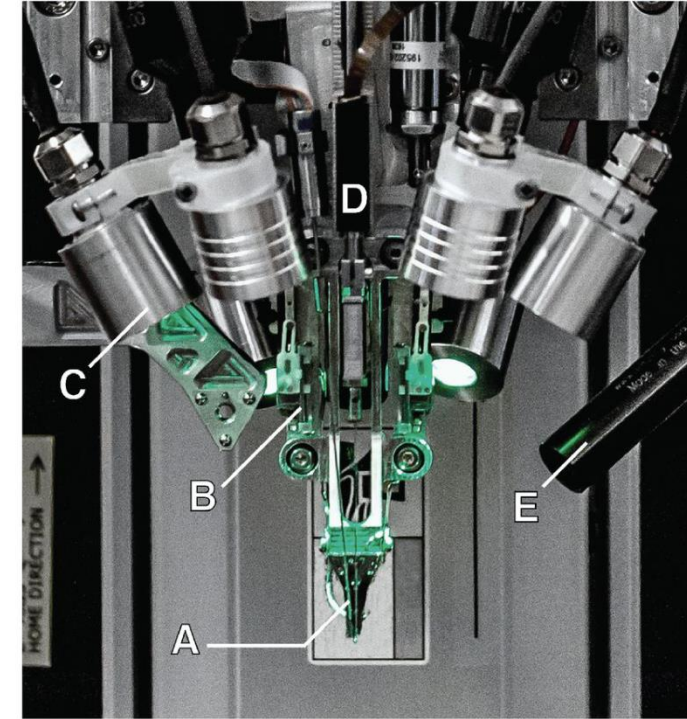
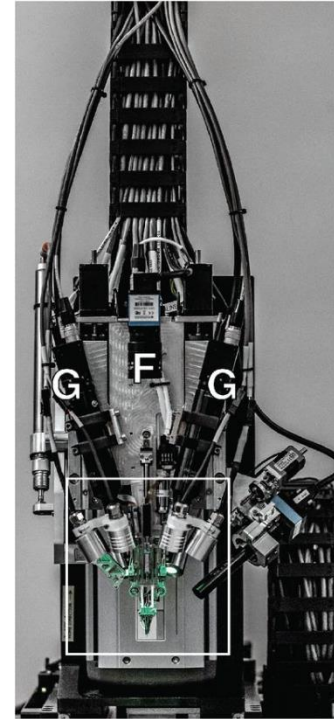


(a) Two clinical neural interfaces: a percutaneous neural recording implant similar to [1], and a deep brain stimulator. (b) Components for an implantable bidirectional (black) or closed-loop (black and gray) wireless neural interface. (c) Example neural interface electrodes. [From left to right (adapted from Utah microelectrode array [6], SENSIGHT by Medtronic [7], ultrathin polymer threads by Neuralink [8], high-density neural matrix [9], Stentrode by Synchron [10], and ultraflexible syringe-injectable mesh [11]).] LNA: low-noise amplifier; ADC: analog-to-digital converter; Tx: transmitter; ML: machine learning; DAC: digital-to-analog converter; Rx: receiver.

# Link v0.9

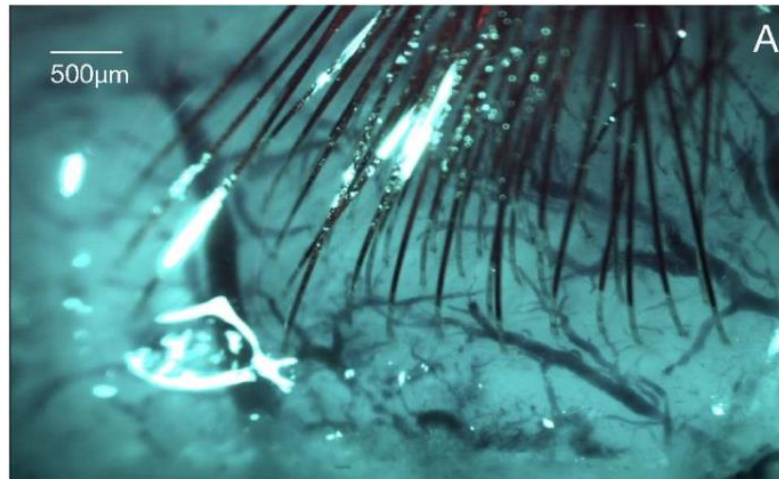


Surgical robots need robotics, **electrical engineering**, mechanical engineering, control engineering



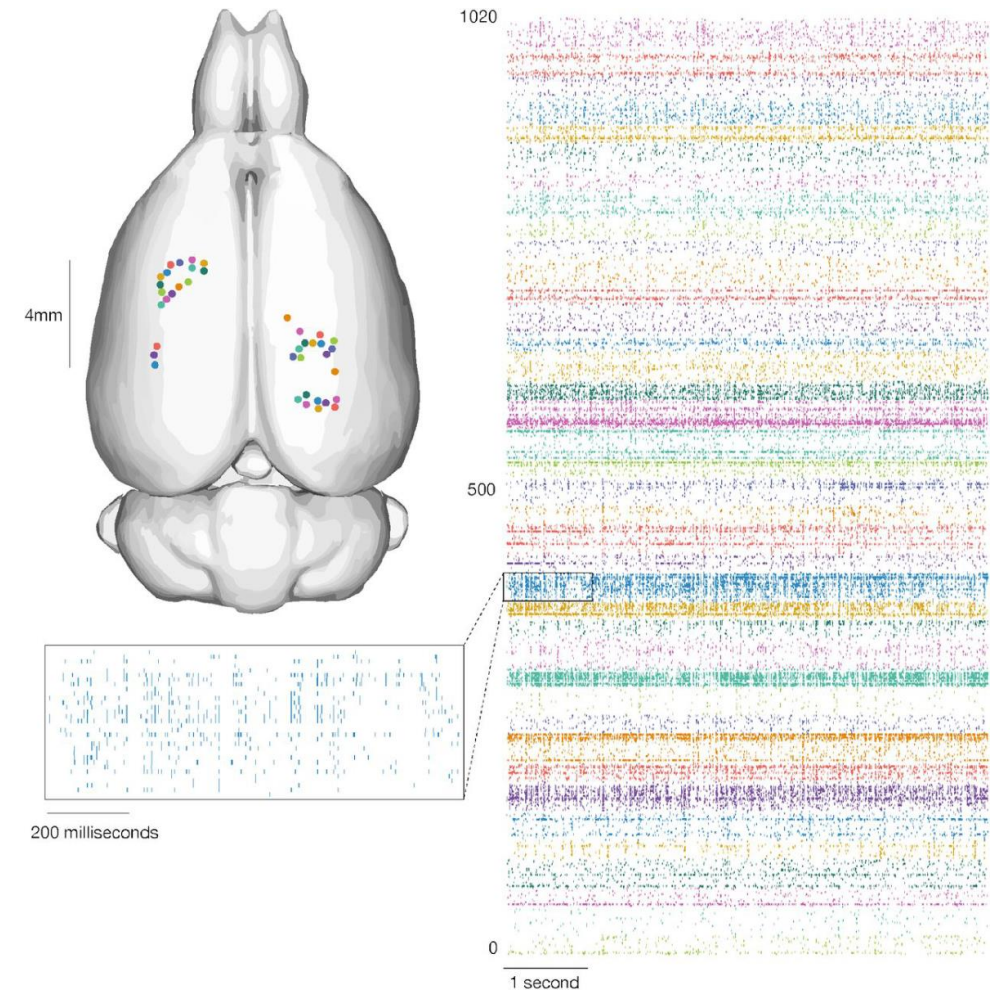
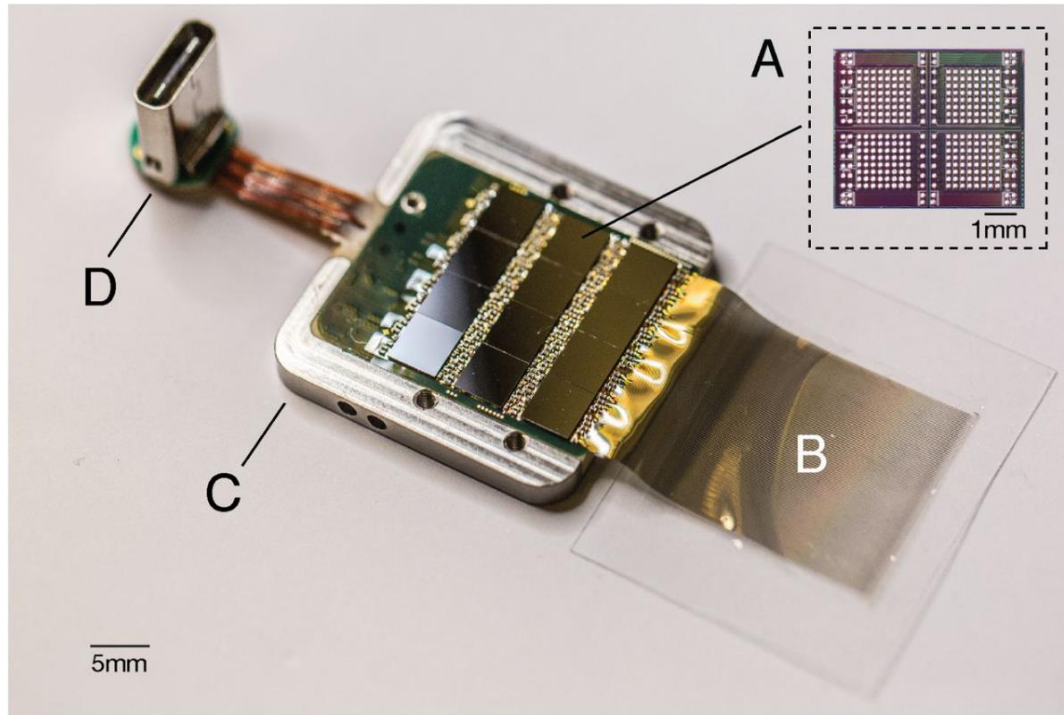
Sensors  
need

**electrical engineering**,  
mechanical  
engineering,  
materials  
science,  
chemical  
engineering



Implants need **electrical engineering**, computer science

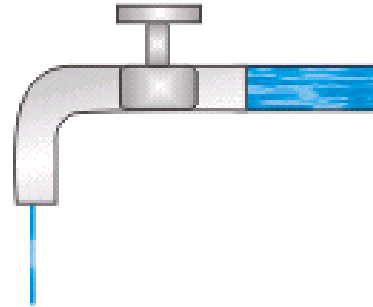
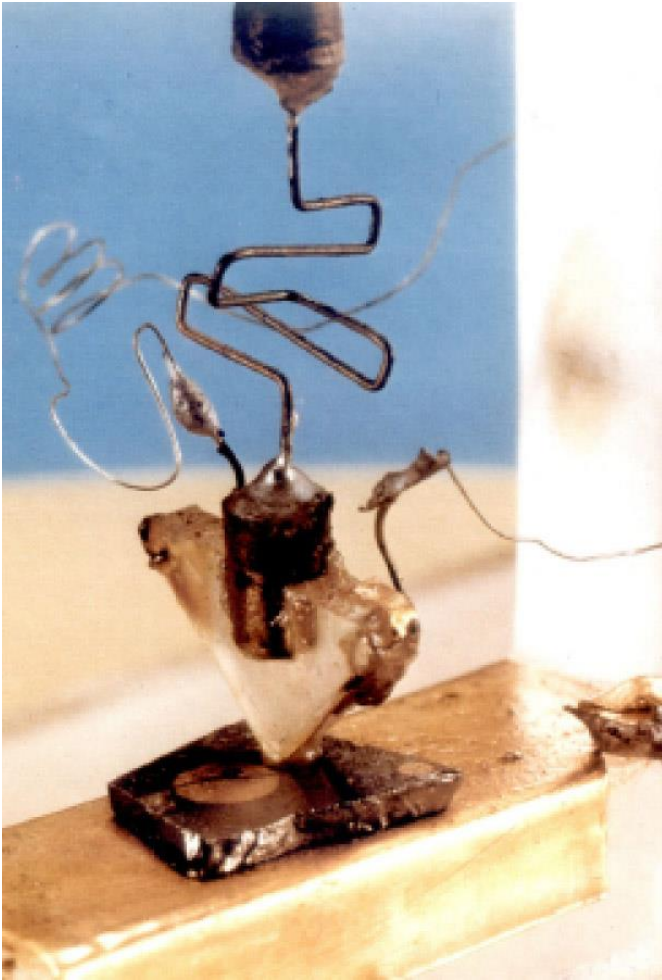
# Brain recording from 1024 analog pixels



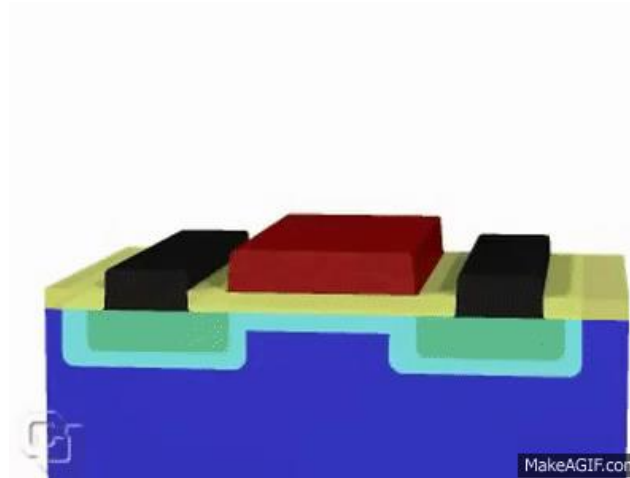
- Each neural recording unit requires sensors, integrated circuits, communications, and power

What is currently driving computing?

# How do we carry out so much computing?



We use  
transistors!



# 1956 Physics Nobel Prize

"for their researches on semiconductors and their discovery of the transistor effect"



**William Bradford Shockley**

🕒 1/3 of the prize

USA

Semiconductor  
Laboratory of Beckman  
Instruments, Inc.  
Mountain View, CA, USA



**John Bardeen**

🕒 1/3 of the prize

USA

University of Illinois  
Urbana, IL, USA



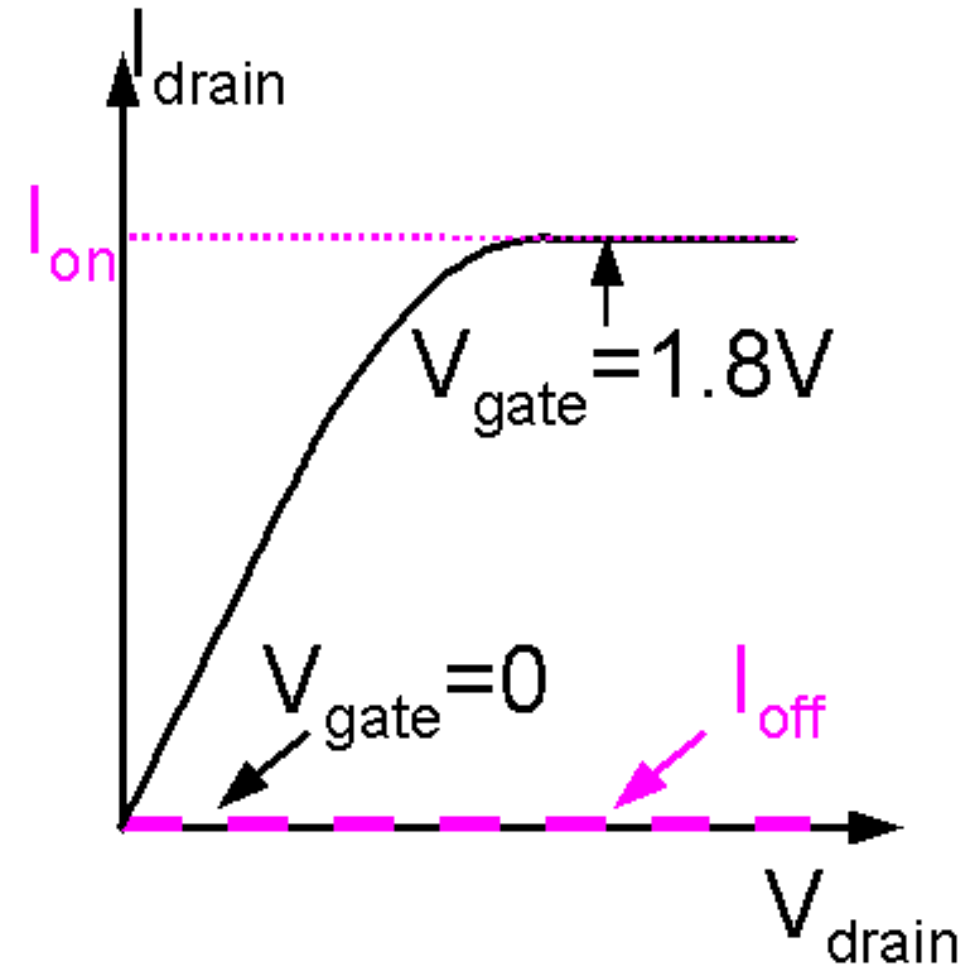
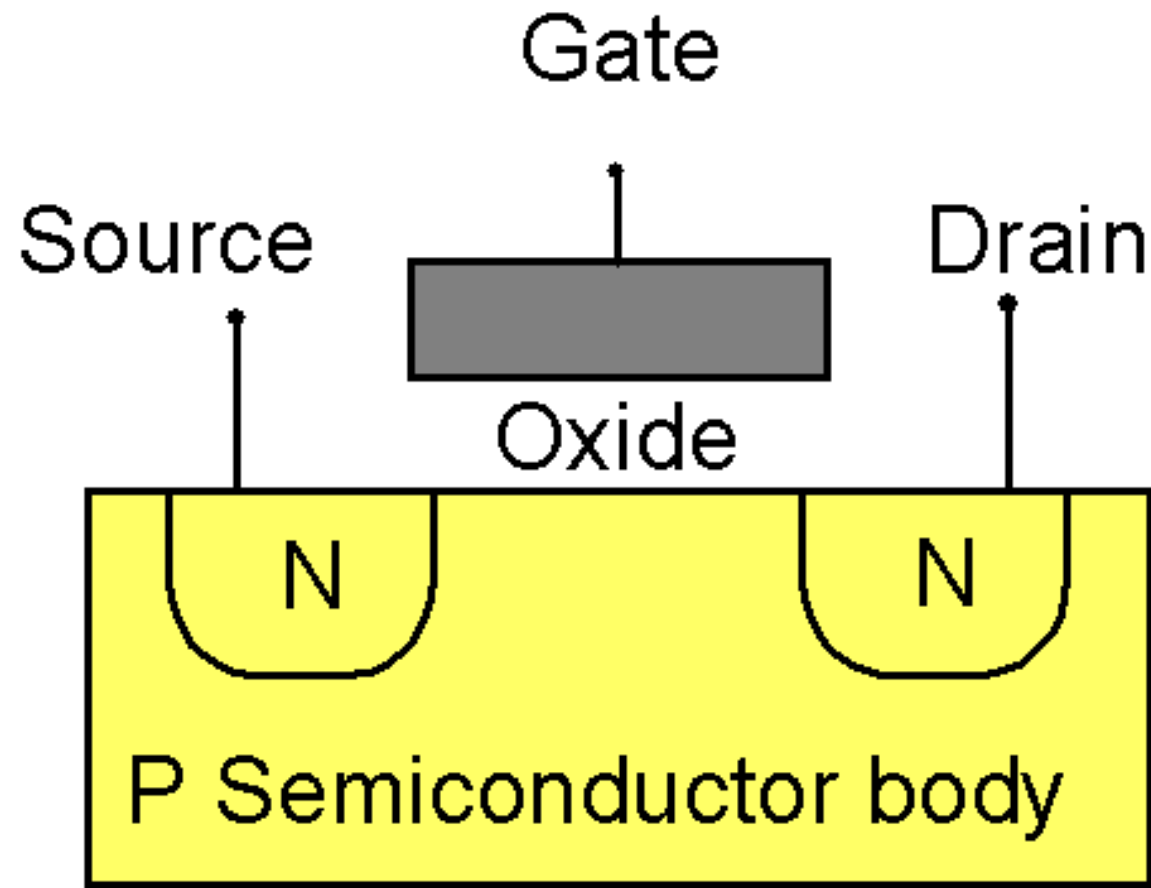
**Walter Houser Brattain**

🕒 1/3 of the prize

USA

Bell Telephone  
Laboratories  
Murray Hill, NJ, USA

# What is a transistor?



What is desirable: large  $I_{\text{on}}$ , small  $I_{\text{off}}$

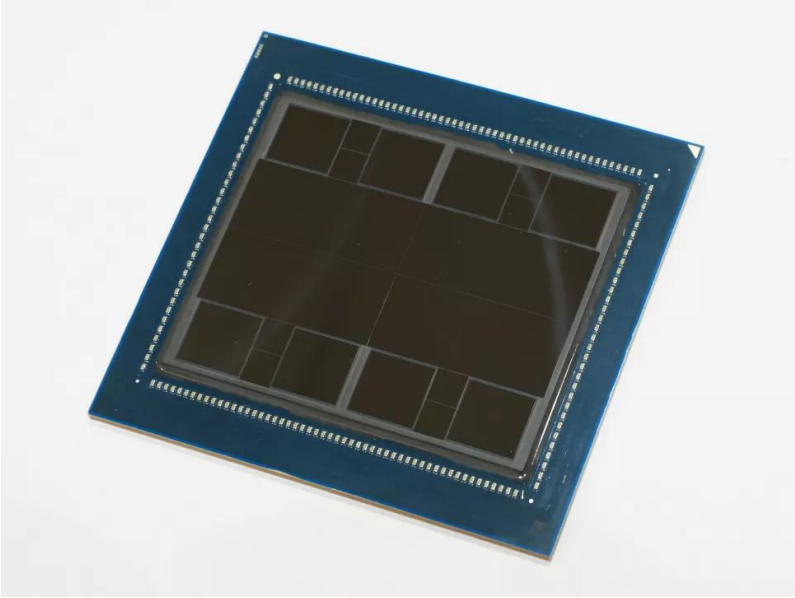
# What is a transistor?

1. It acts as an on-off switch.
2. We want to switch it on and off as fast as possible.
3. We want to switch it on and off with as little power usage as possible.

What is desirable: large  $I_{on}$ , small  $I_{off}$

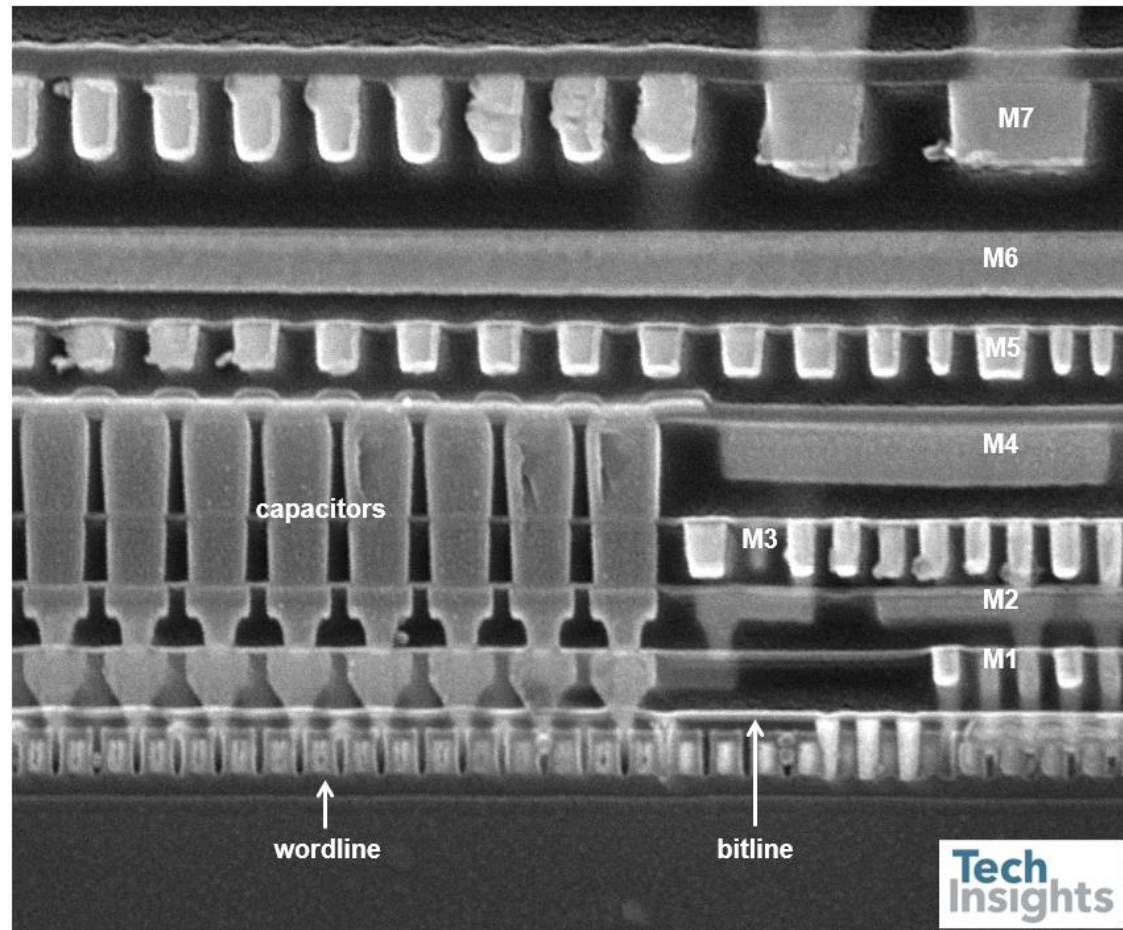
# What do modern day integrated circuits look like?

## AMD Instinct MI300 Accelerator



- Key points
  - Total of ~150 billion transistors
  - Uses 5 nm node technology
    - Density of transistors is ~130-230 million transistors/mm<sup>2</sup>
    - In the area of a cell, we could fit ~100k - 1 million transistors
- Multiple parts of this processor use 3-D stacked dies
  - Enables computing, memory, sensing, and stimulation to be integrated together
- Performance ~8x improved over previous MI250 Accelerator
  - If they upgraded the fastest supercomputer to this part, they could train the largest AI/ML systems

# What do these look like?

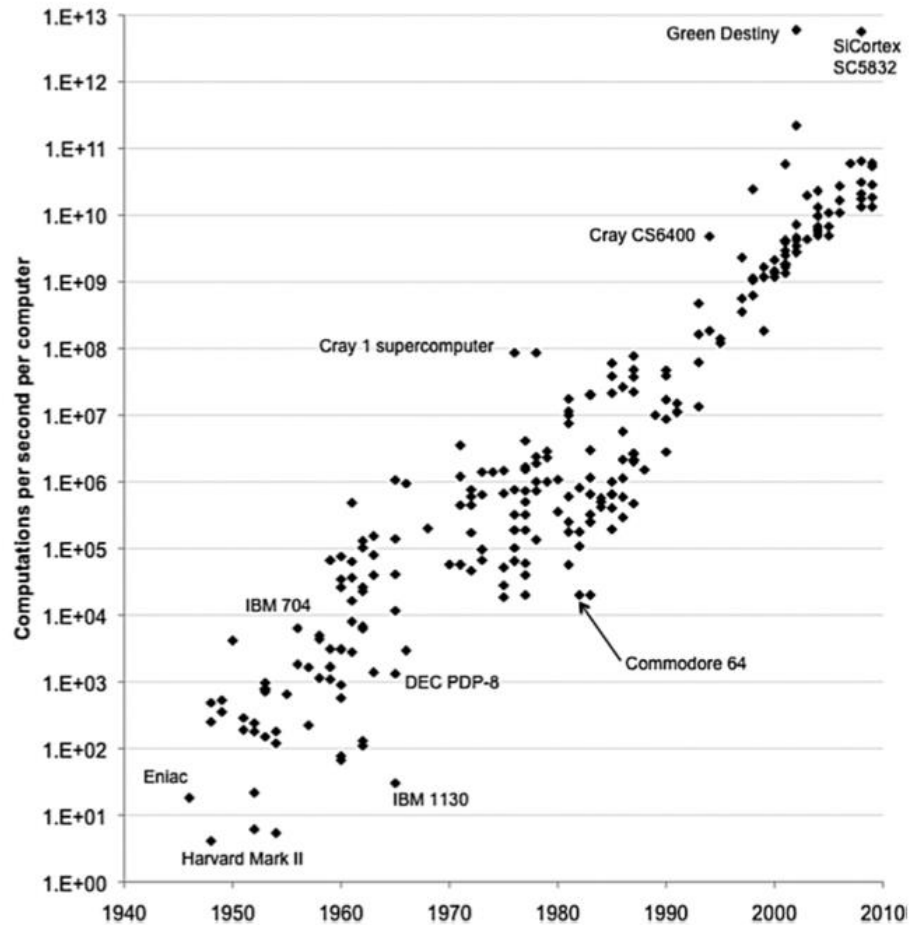


Wires to connect all the transistors together

Active devices (silicon transistors)

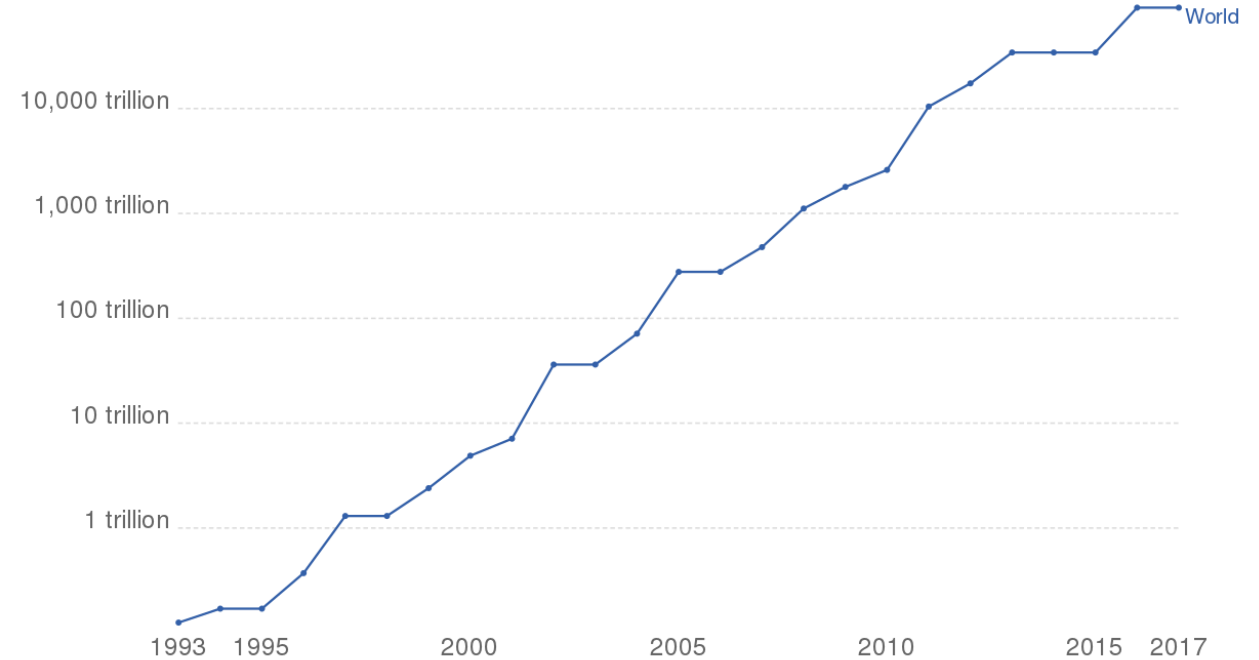
How did we get here?

# How much has computing power increased?



## Supercomputer Power (FLOPS)

The growth of supercomputer power, measured as the number of floating-point operations carried out per second (FLOPS) by the largest supercomputer in any given year. (FLOPS) is a measure of calculations per second for floating-point operations. Floating-point operations are needed for very large or very small real numbers, or computations that require a large dynamic range. It is therefore a more accurate measure than simply instructions per second.



Source: TOP500 Supercomputer Database

- From 1990 to today, the worlds largest super computers have increased computing power by 100,000x
  - That's a lot!

# The First Moon Landing Was Achieved With Less Computing Power Than a Cell Phone or a Calculator



On board Apollo 11 was a computer called the Apollo Guidance Computer. It had 2,048 words of memory that could be used to store “temporary results”—data that is lost when there is no power. This type of memory is referred to as RAM (random access memory). Each word comprised 16 binary digits (bits), with a bit being a zero or a one. This means that the Apollo computer had **32,768 bits of RAM memory**.

My computer has 64,000,000,000 bits of RAM memory

That is 2,000,000 times more than what was needed in Apollo 11.

How do we make transistors faster?

# Scaling – How much have we scaled devices?

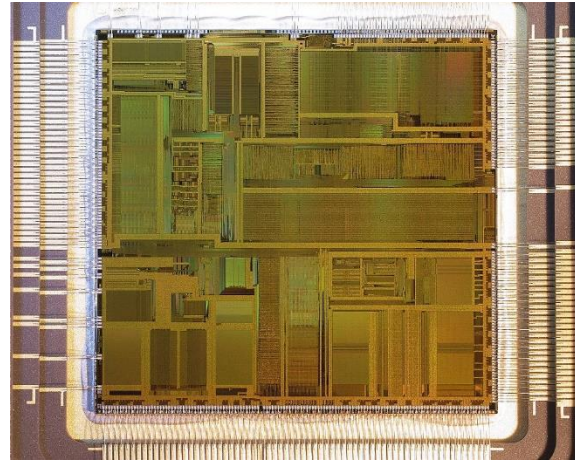
- 1971: The first commercial microprocessor...Intel 4004
  - 4-bits
  - Less than 1 square inch in area
  - Transistors that were 10 micrometers long
  - ~750 kilohertz speed
  - ...but more powerful than the computers from earlier that weighed 30 tons



Let's say that this is a scaled version of how long a transistor was in 1971

# Scaling – How much have we scaled devices?

- 1990s: The first Pentium processor
- 66 MHz. That's 100 times faster than in 1970.
  - Can you think of anything else that has improved by 100x in 20 years?

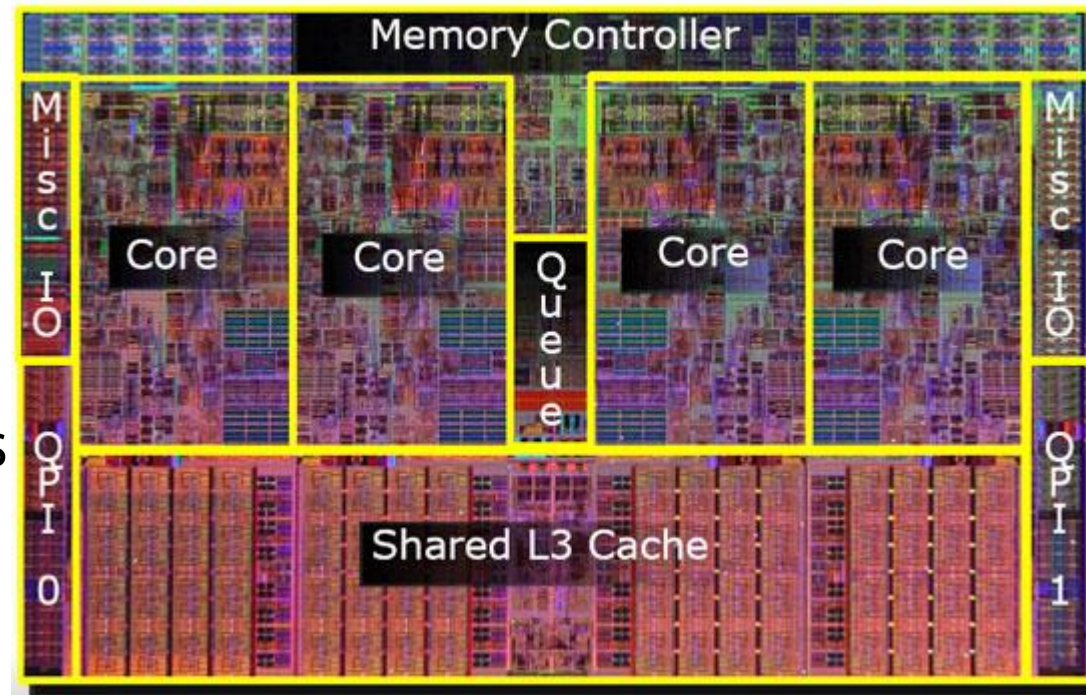


1971

1993

# Scaling – How much have we scaled devices?

- 2012:
  - 1-3 GHz
  - Multi-core
  - Super-fast
  - Each transistor is almost 1000 times smaller!

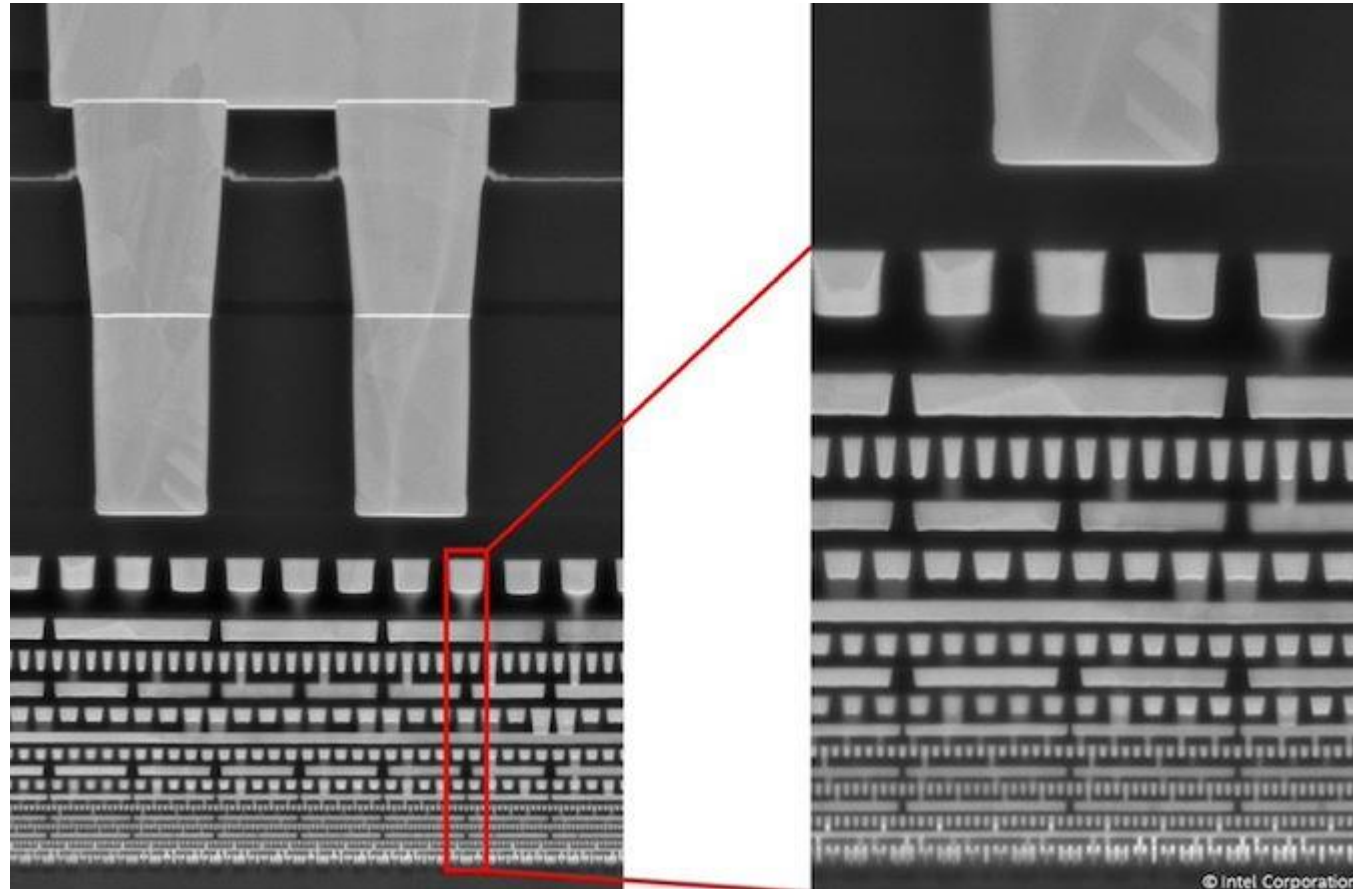


1971

1993

Can't even see the size on the screen...not enough pixels

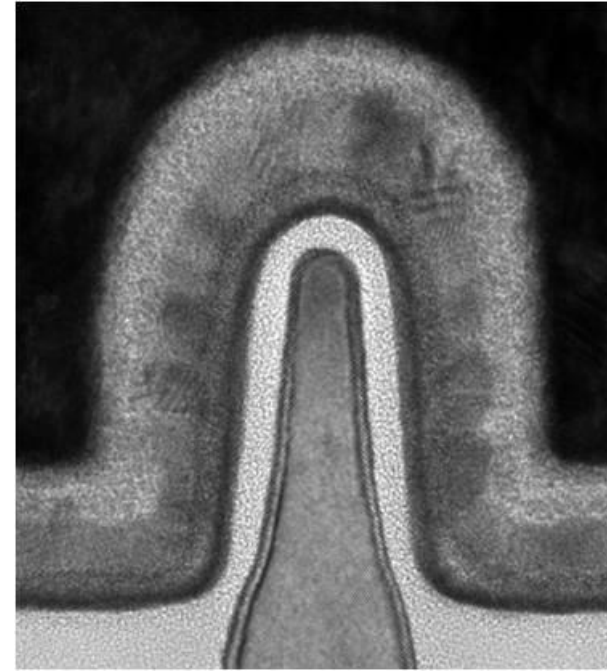
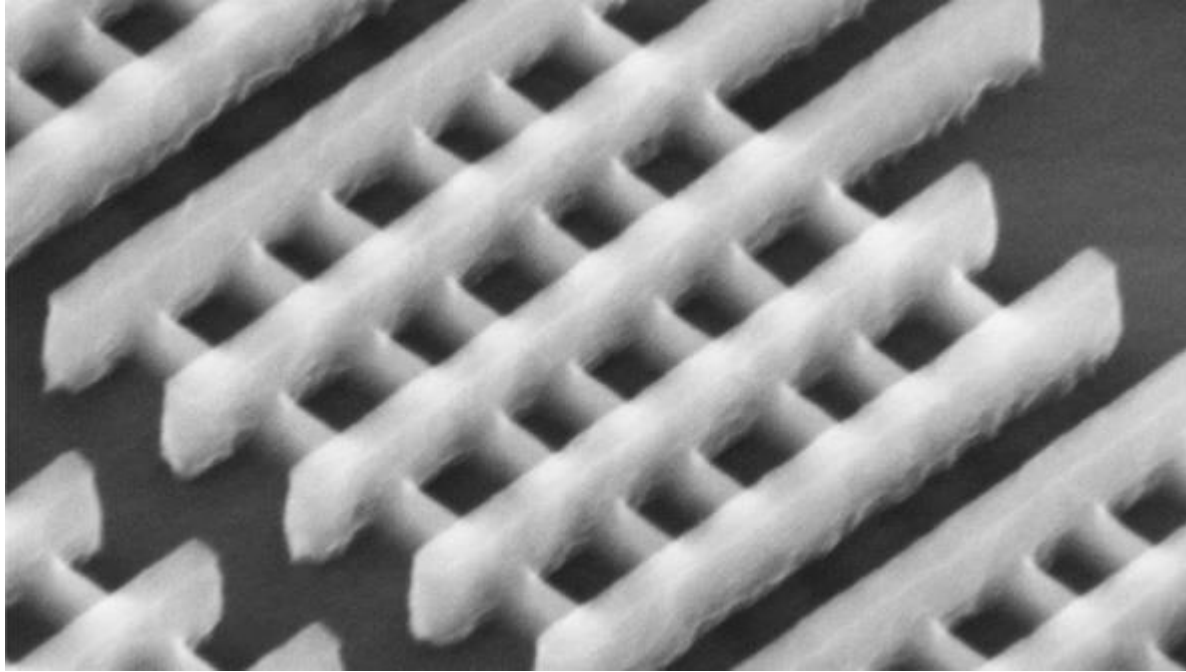
# Scaling – How much have we scaled devices?



Intel 4 cross section:  
to be released 2023

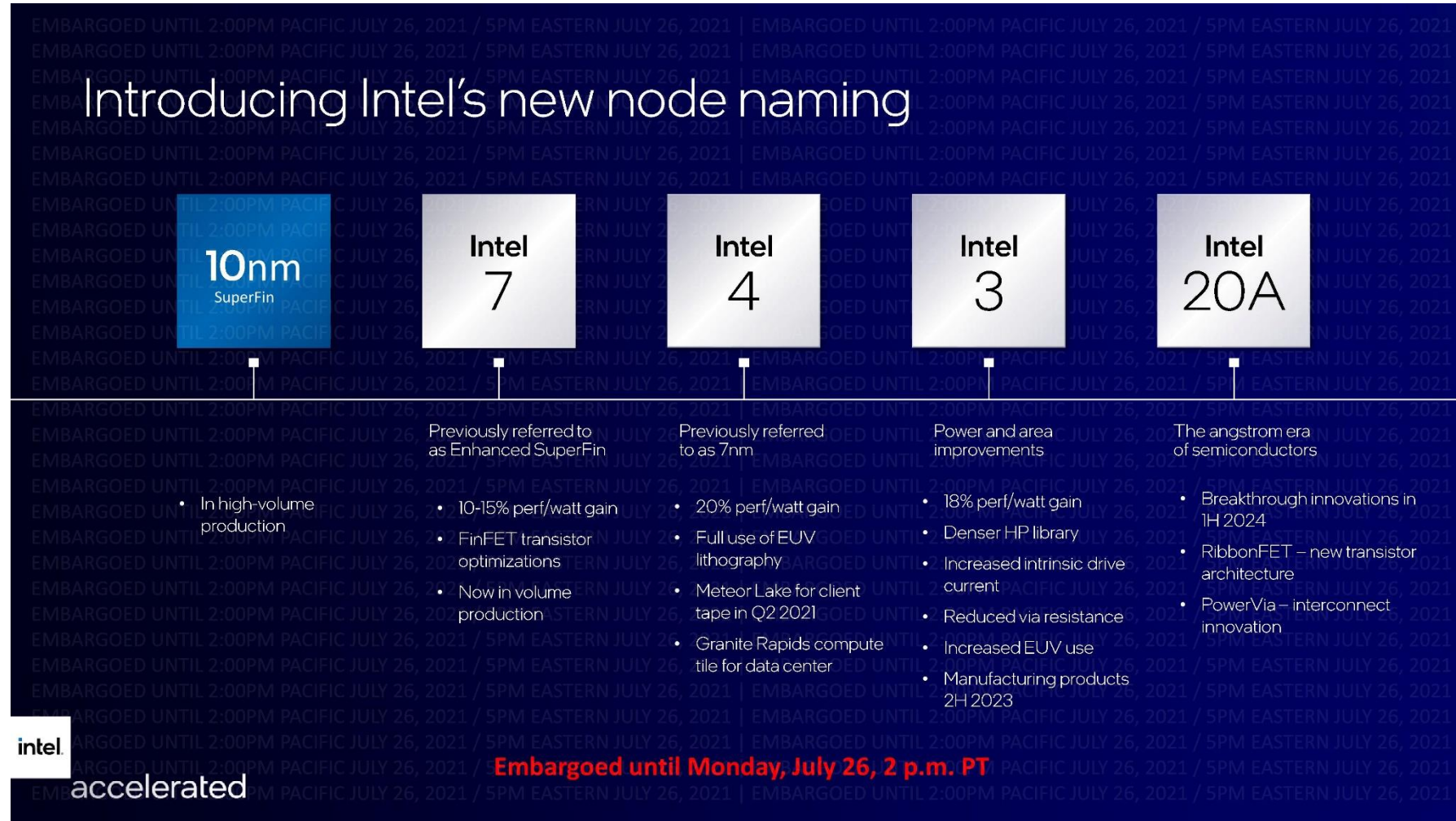
- What does a modern CPU cross section look like?
  - Where are the transistors?
  - What are we looking at?

# FinFET Transistors (May 2011 and After)



- FinFETs
  - Why is it called that?
  - What do you think the advantage is?

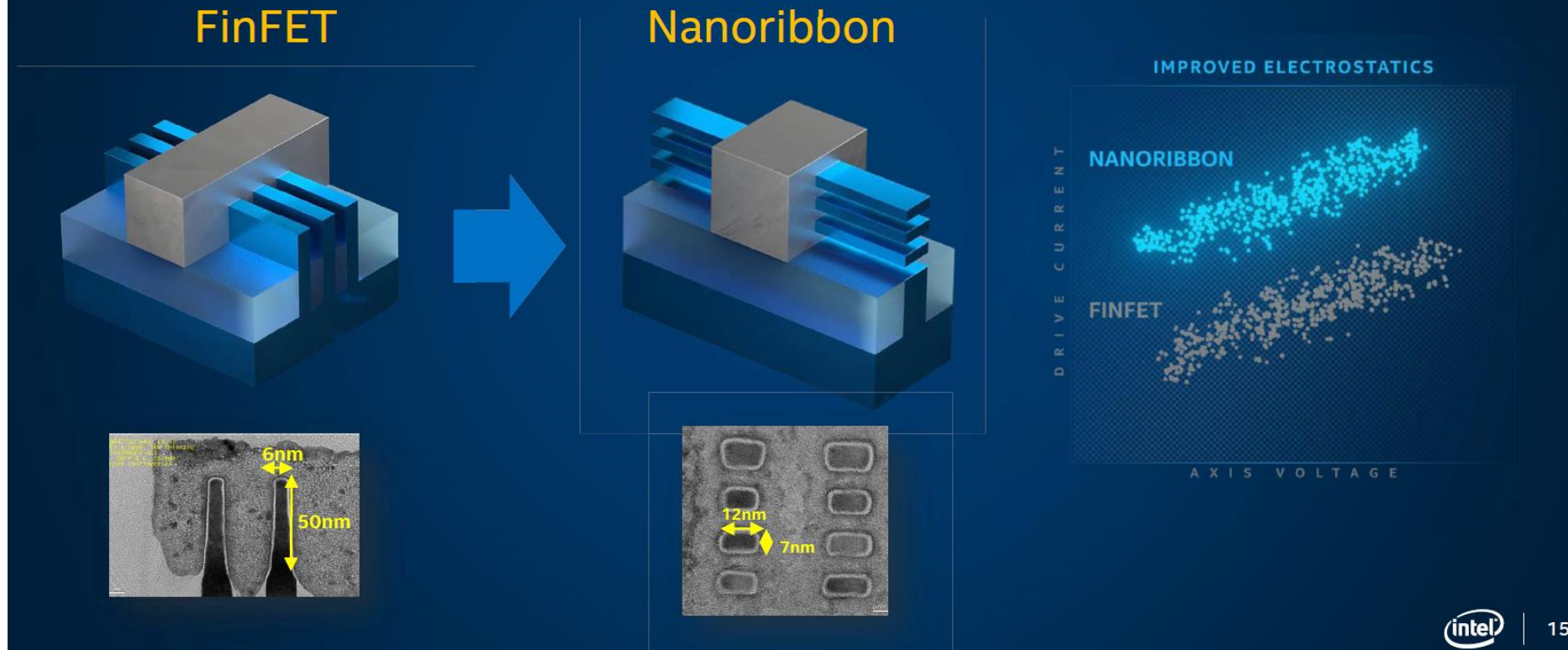
# Scaling – How much have we scaled devices?



- This is a recent roadmap for Intel's transistor scaling plans

# Scaling – How much have we scaled devices?

## FINFET CHANGING TO NANOWIRE/NANORIBBON

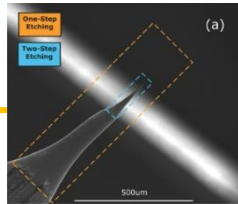


- What is a Nanoribbon FET?
  - Why does it give better performance?

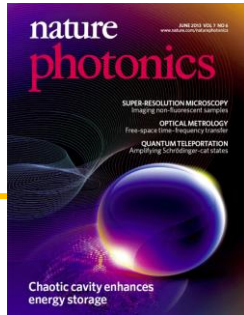
# My background and research



BS, EE, 2010



Electrical Engineering  
and Materials Science

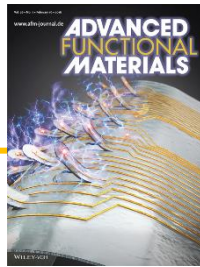


MS, EE, 2012

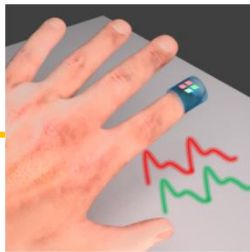
Started PhD, 2013



Flexible Hybrid  
Electronics  
2016



2015



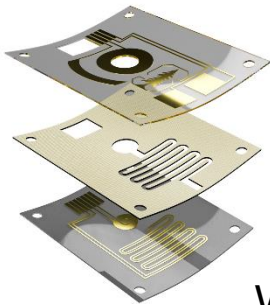
2014

Bioelectronic and  
Biophotonic  
Systems

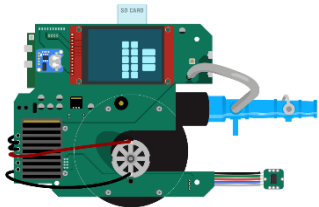
Stanford

Started  
postdoc, 2019

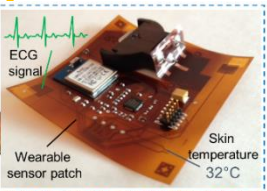
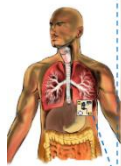
PhD,  
EECS,  
2018

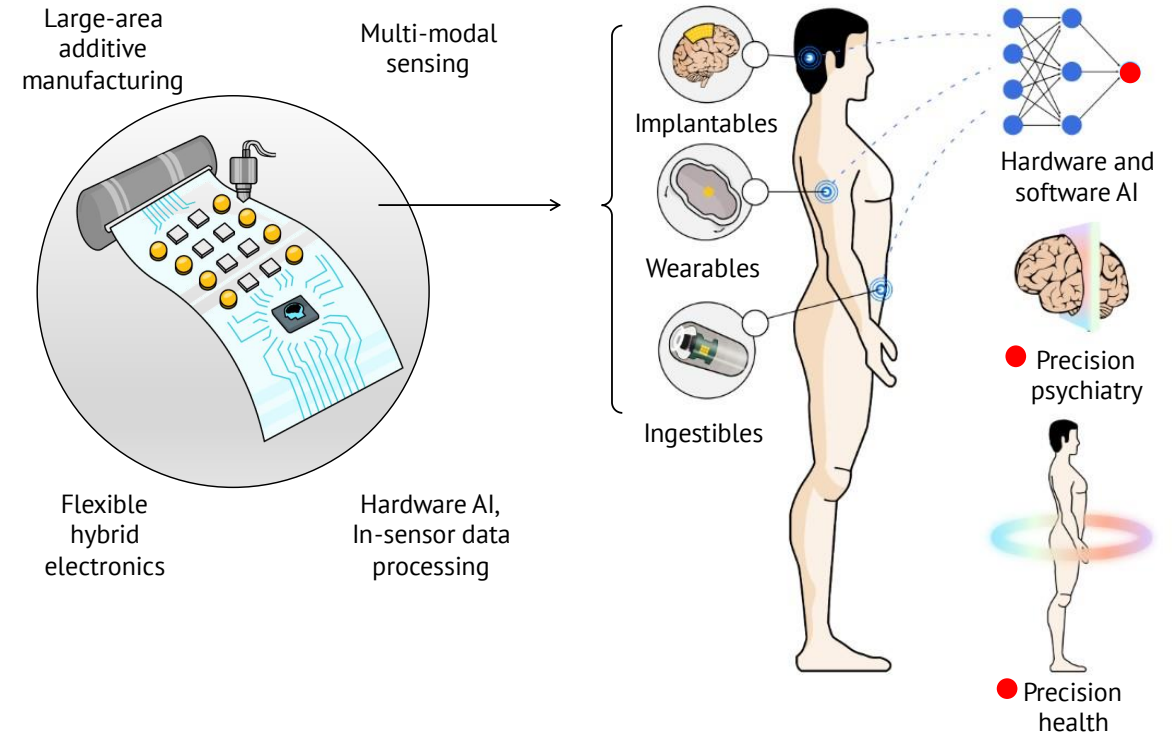


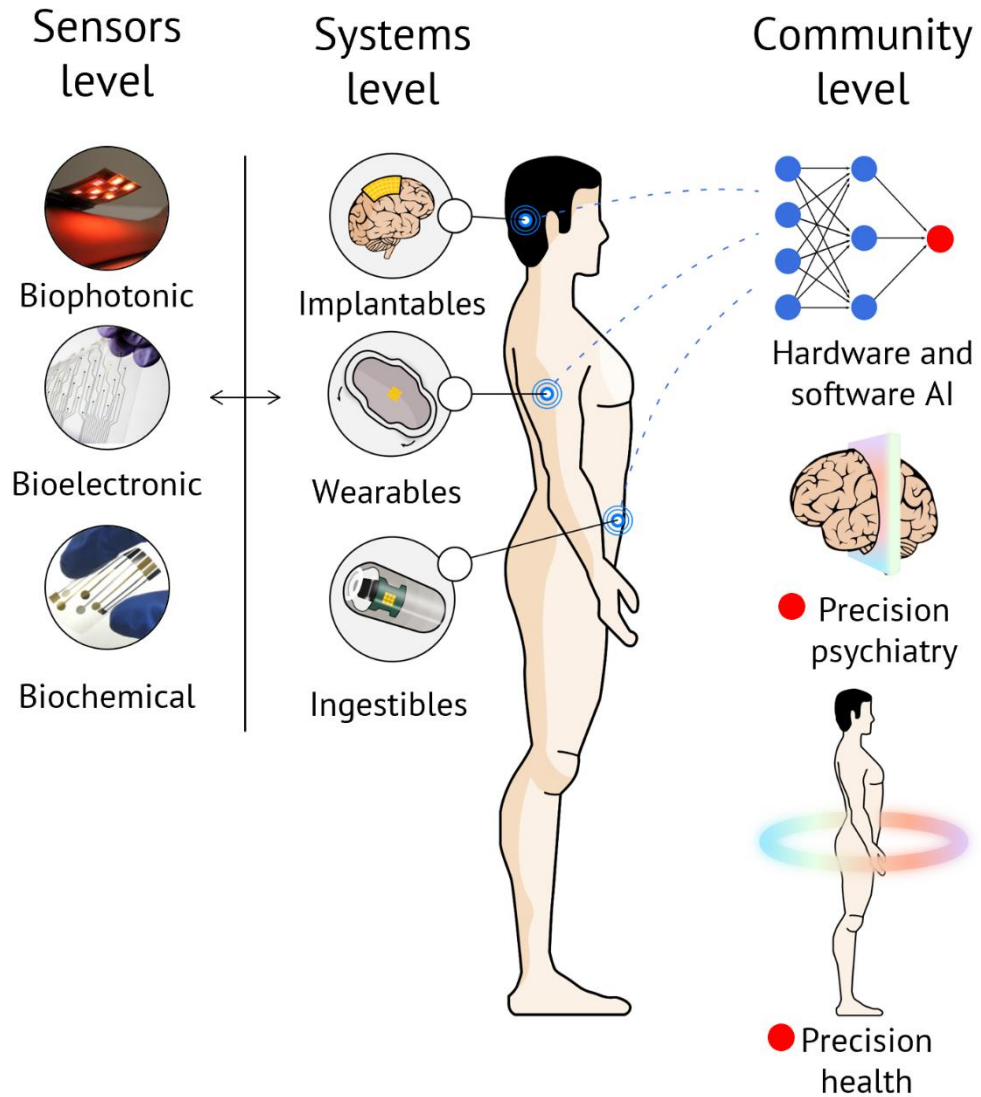
Wearables for  
precision health  
and psychiatry



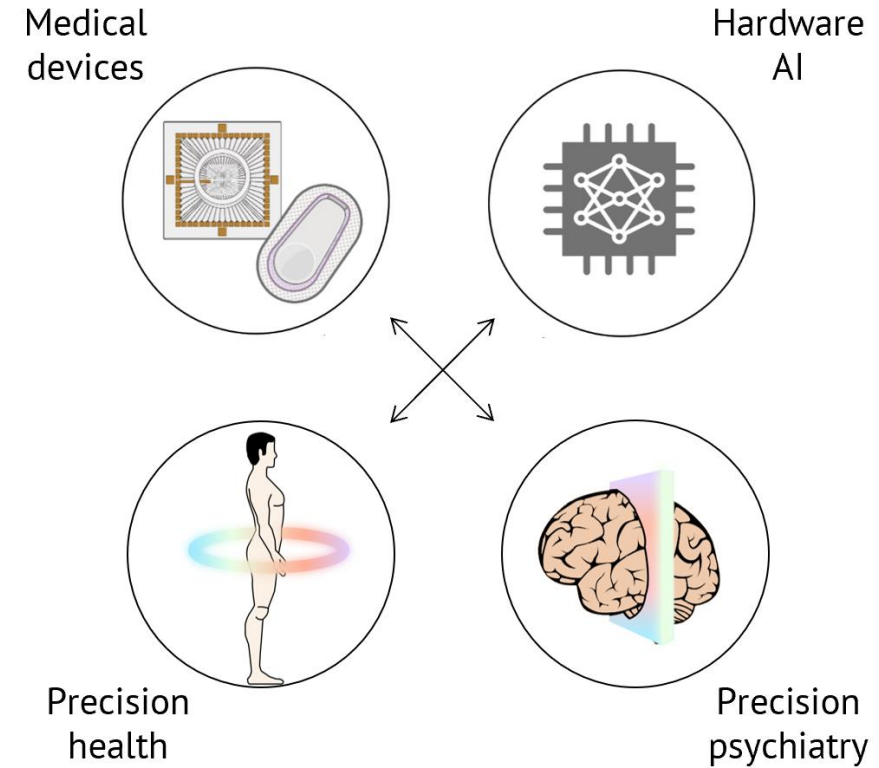
Ventilator for  
COVID-19



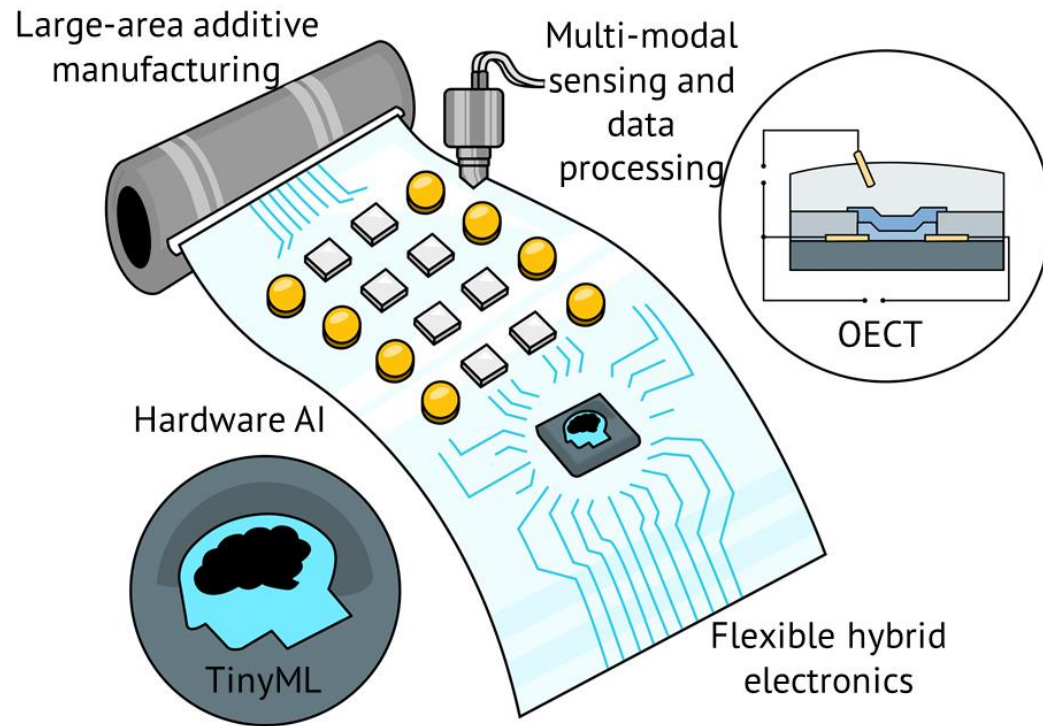




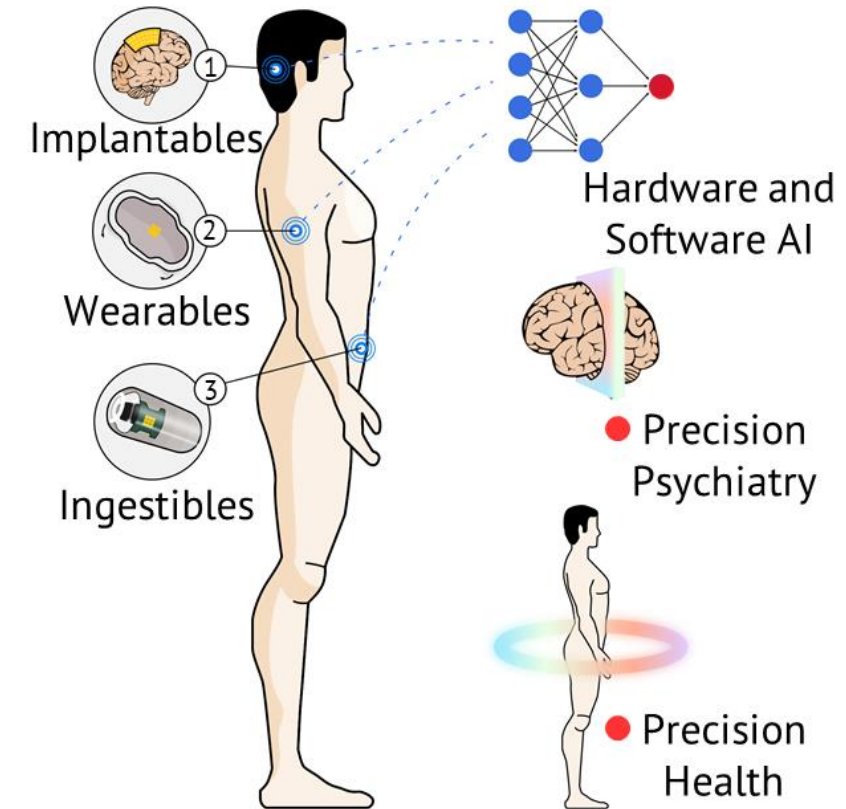
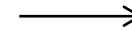
## Research Focus



# Soft sensor systems for precision health and psychiatry



Materials,  
Manufacturing, Design,  
Devices, and Circuits



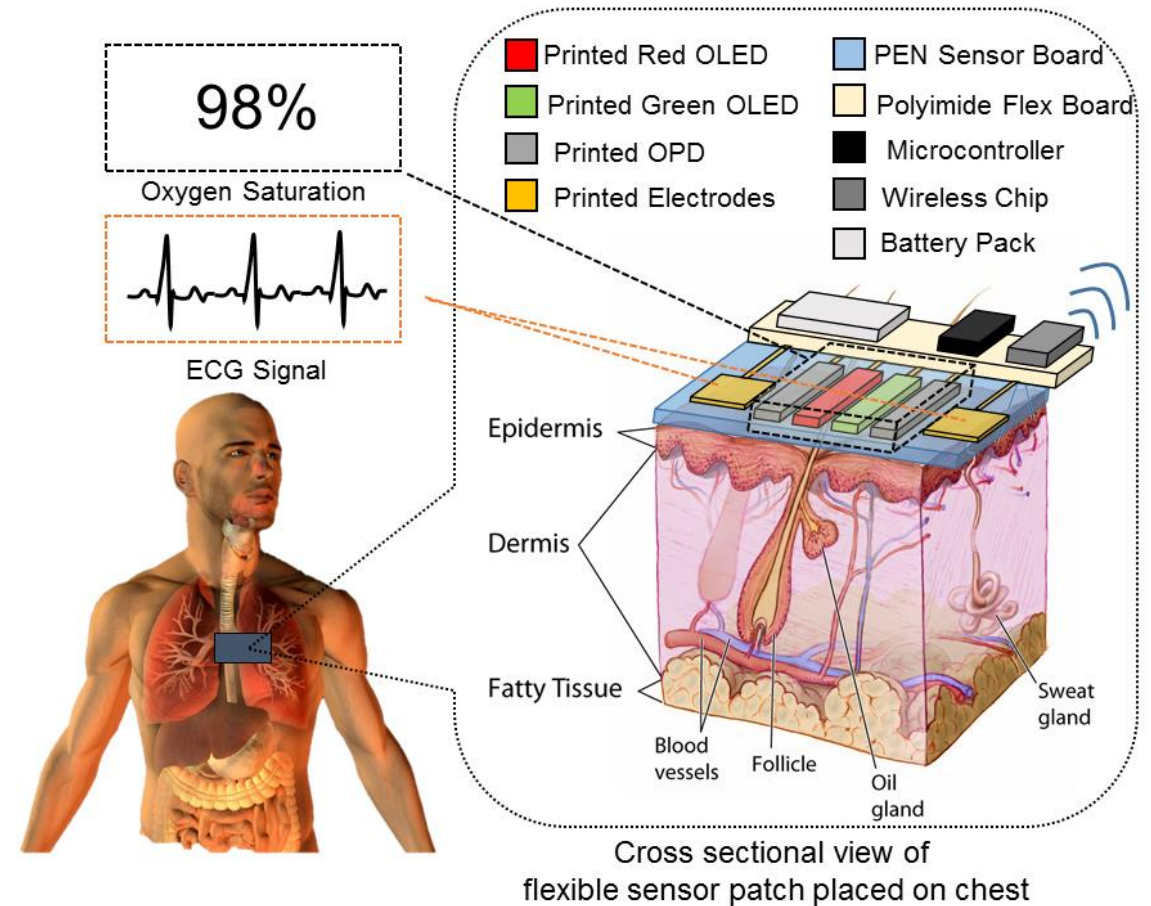
Systems and  
Applications

# Sensors for precision health and psychiatry



## Current state:

Big machines with a lot of wired rigid sensors that limits the comfort of the patient



## Vision:

A flexible sensor patch that seamlessly measure vital signs - measurements of the body's most basic functions

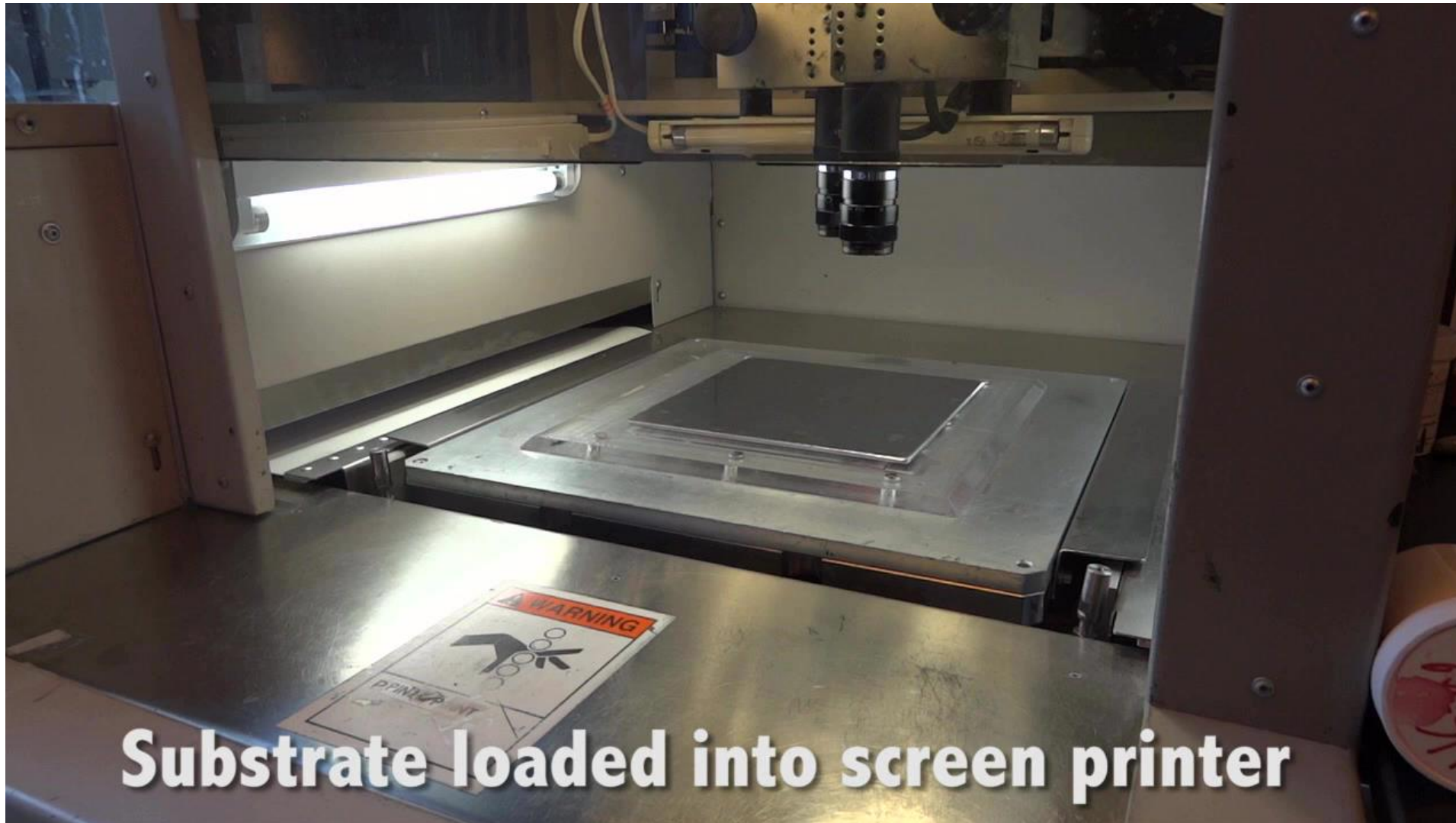
- Biopotential sensing for gesture recognition

## FlexEMG

HIGH-DENSITY FLEXIBLE EMG-BASED GESTURE RECOGNITION WEARABLE DEVICE USING  
HYPER-DIMENSIONAL COMPUTING

Berkeley  
UNIVERSITY OF CALIFORNIA

# Screen-printed MRI receive coils

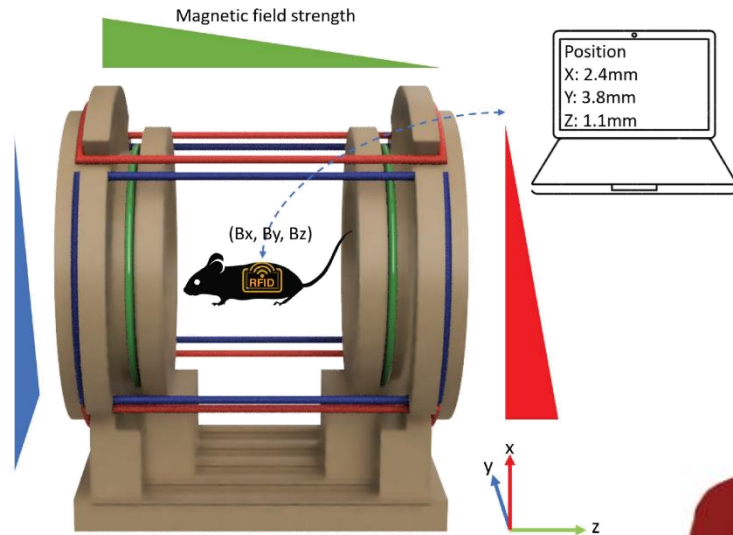


**Substrate loaded into screen printer**

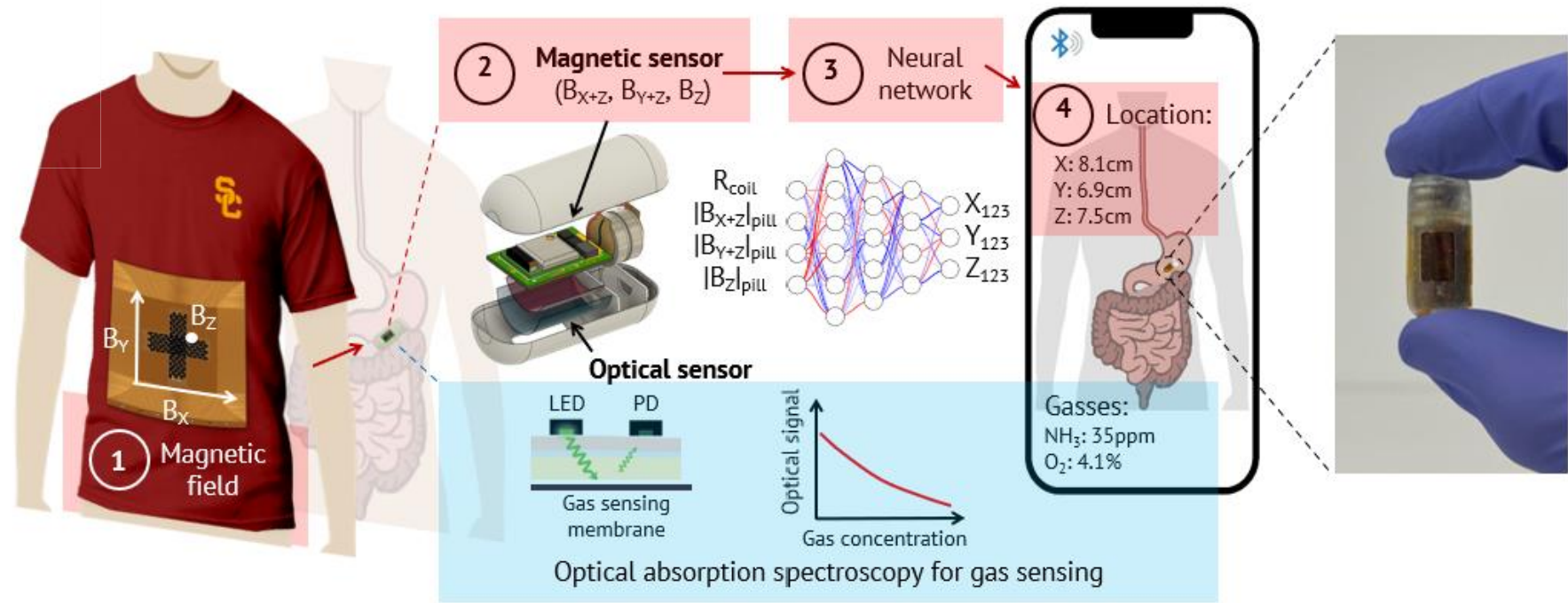
- High-throughput.
- Scalable.
- Fast.
- Significantly less process steps compared to photolithography.

# 3D gas mapping in the gut with AI-enabled ingestible and wearable electronics

Existing approach: Helmholtz coil for producing a region of nearly uniform magnetic field and localizing ingestible inside the coil.



Our approach:  
Wearable multi-layer  
coil for 3D field  
gradient, and use a  
bend sensor for  
accounting for  
movement.



# 3D gas mapping in the gut with AI-enabled ingestible and wearable electronics

## From Wearables to Swallowables: USC Engineering Researchers Create GPS-like Smart Pills with AI

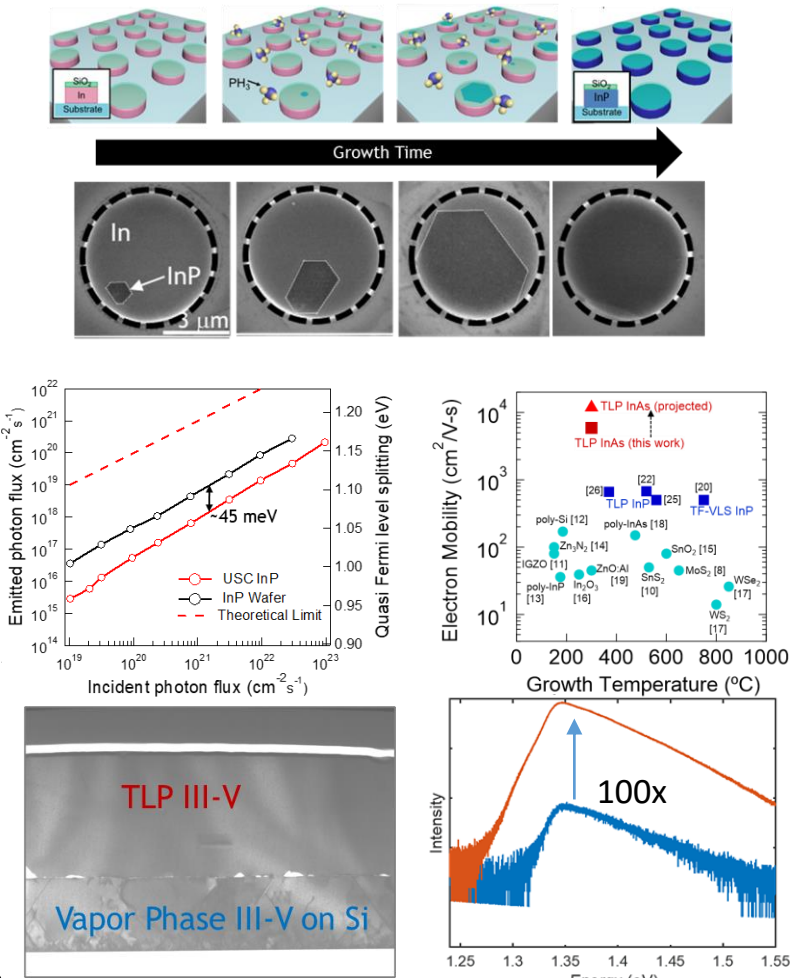
[Amy Blumenthal](#) | June 12, 2024

Utilizing wearable electronics and AI, new ingestible sensors provide real-time 3D monitoring of gastrointestinal health

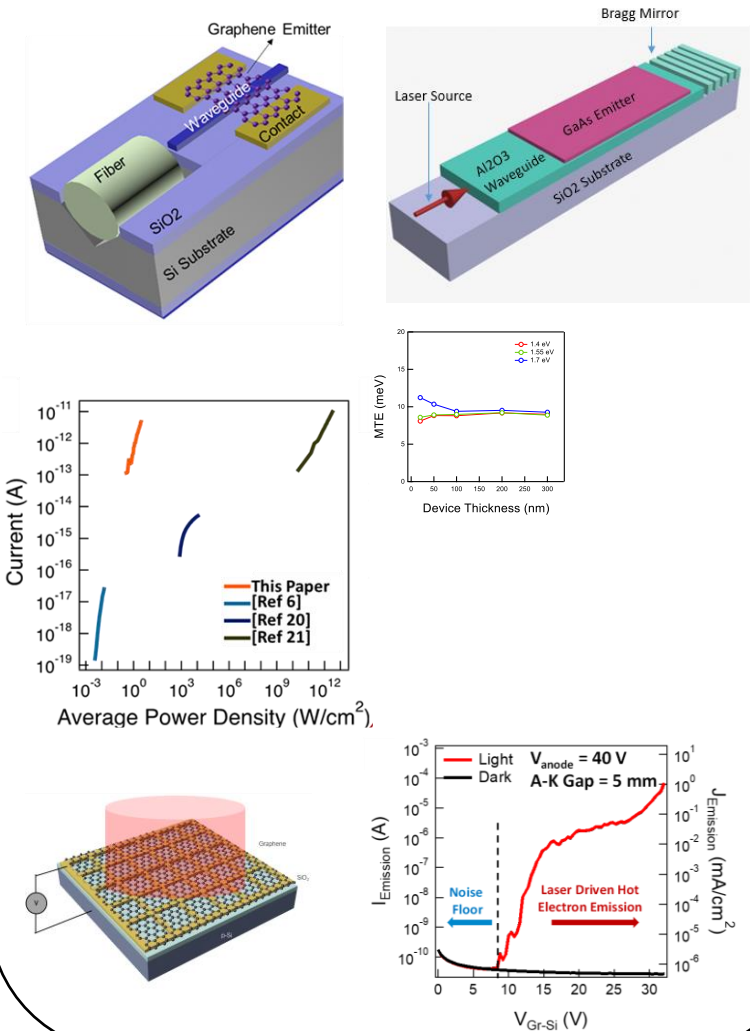


AN INGESTIBLE SMART SENSOR COULD DETECT CANCERS. IMAGE CREDIT: THE KHAN LAB

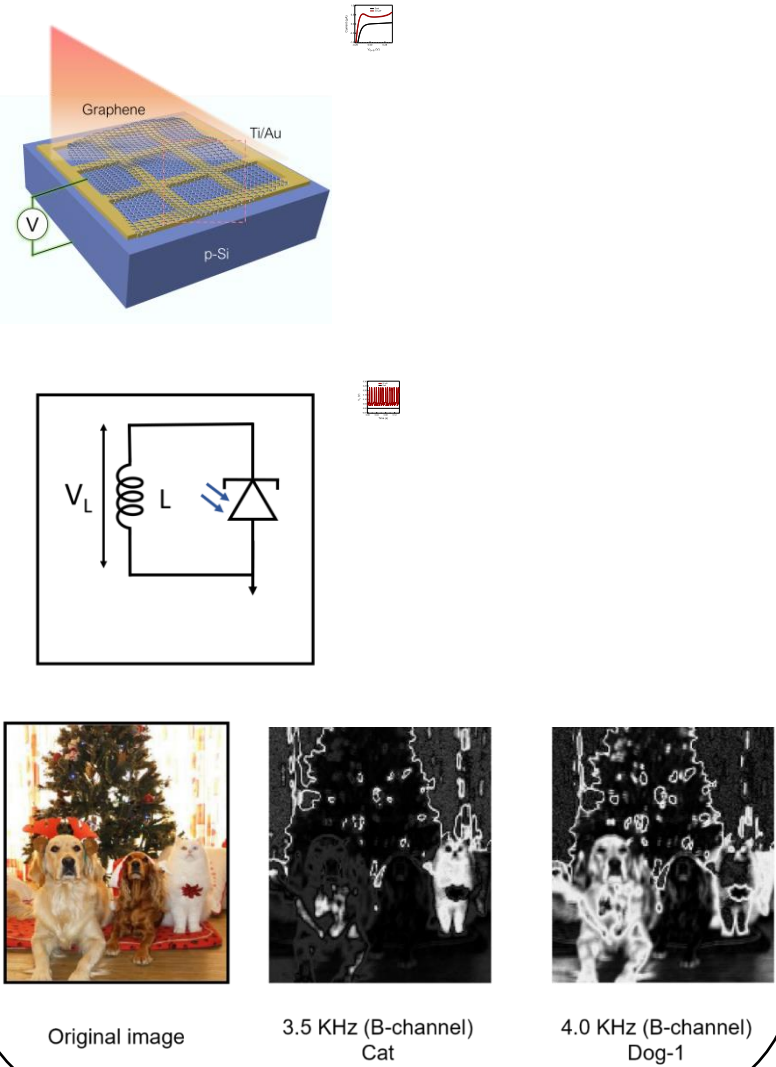
### Back-End Materials Growth and Heterogeneous Integration



### Electron Emission Devices for GHz to THz Applications



### Ultra-Low Power Computing



# John O'Brien Nanofabrication Laboratory



Etch

Deposition

Lithography

Wet Processing

Packaging

Infrastructure

- \$50M 12,000 Sq. ft. facility
- +24,000 sq. ft. automated facility for facilities, gases, and support systems
- 35+ state-of-the-art cleanroom tools including e-beam and direct write tools, Si and compound semiconductor processing
- Sample size from pieces to 100mm (min) and 150mm (subset – but all III-V)

## Scalability:

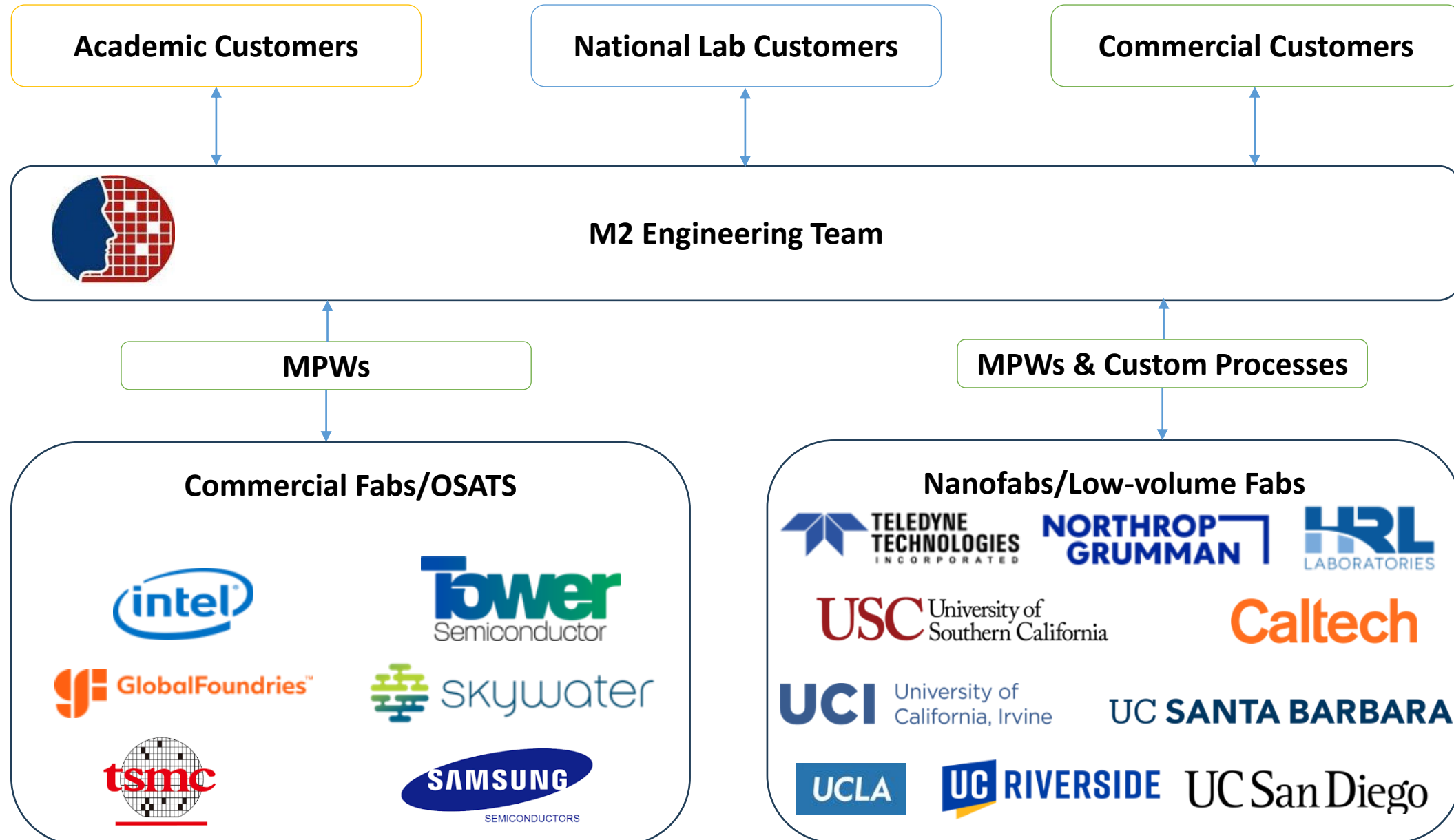
- +200 users (2024) with expansion to +500 users planned. The lab can handle 100 active users.
- Space available within current facility for additional capacity and capability

# The MOSIS Service: Background and History

- The MOSIS Service was founded in 1981 at Information Sciences Institute, Viterbi School of Engineering of University of Southern California
- DARPA provided the contract for The MOSIS Service to facilitate the first manufacturing projects for fabless organizations
- The MOSIS Service pioneered the Multi-Project Wafer (MPW) model
- The MOSIS Service has processed over 60,000 designs at more than a dozen foundries
- Customers of The MOSIS Service have included US Government Laboratories, foreign and domestic corporations, and foreign and domestic universities
- MOSIS has enabled IC designers to prototype innovative semiconductor designs in CMOS FinFET, FD-SOI, Bulk, III-V Compound, high-voltage BCD, and other specialty processes



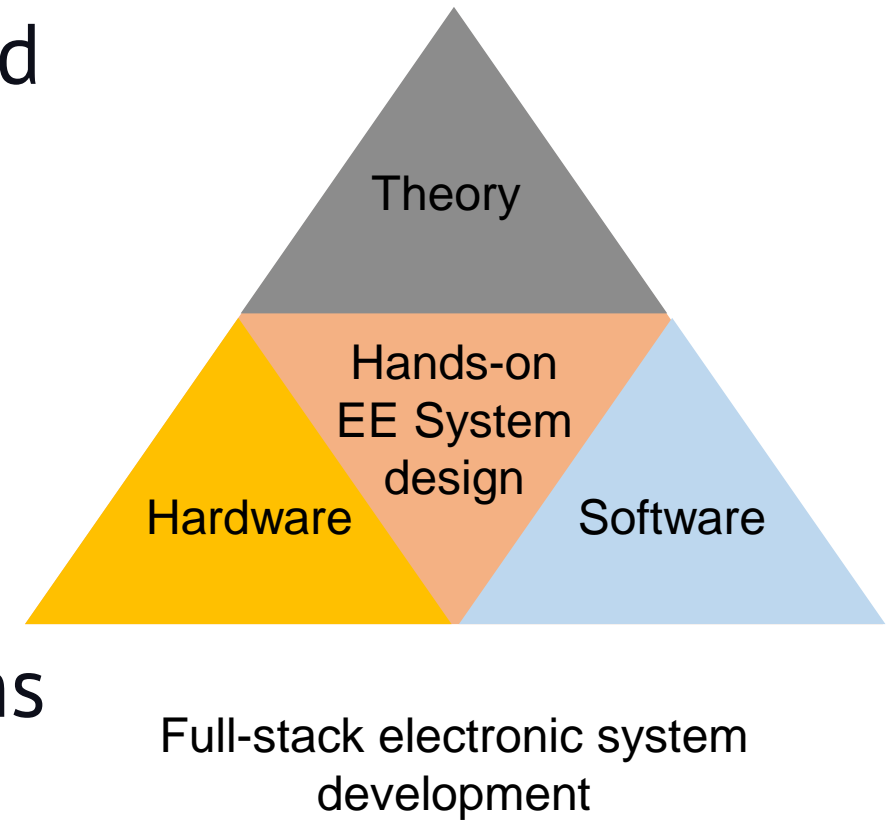
# Overview of MOSIS 2.0



# Overview of MOSIS 2.0 – MPW Offerings

Foundry	Technology	Nodes (nm)
Intel	Si CMOS	16, 22
Skywater	Si CMOS	90, 130
TSMC	Si CMOS	12, 16, 22, 28, 40, 45, 55, 65, 90, 130, 180, 250, 350
Samsung	Si CMOS	28, 65, 130
WIN Semi	GaAs pHEMT	100, 150, 180, 250, 450, 500
WIN Semi	GaN HEMT	120, 150, 250, 450
WIN Semi	GaAs HBT	7 <sup>th</sup> Gen, 5 <sup>th</sup> Gen, 4 <sup>th</sup> Gen
Northrop Grumman	Under Development	GaN GaN20_PWR; InP N60; GaAs P3H; GaAs P3K; GaAs P3D;
Teledyne	Under Development	InP N60
Global Foundries	Under Development	Si CMOS ; RF SOI; RF SiGe; SiPh SOI
Tower Semi	Under Development	SiGe
HRL	Under Development	GaN T3

- Understand theoretical and practical concepts in electrical engineering.
- Overview of devices, circuits, systems, and AI/ML tools.
- Design simple biosensor systems from end to end.
- Design imager systems with embedded ML.
- Design and implement electronic systems for given specifications.



- Dynamic syllabus:

<https://drive.google.com/file/d/1HjTI33m4UouCzfoHWDAXYqaWjObf419k/view?usp=sharing>



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Prof. Rehan Kapadia

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Vikas Addepalli (Course Mentor)

Emails: [daddepal@usc.edu](mailto:daddepal@usc.edu)



Walter Unglaub  
(Research Engineer)

Emails: [unglaub@usc.edu](mailto:unglaub@usc.edu)

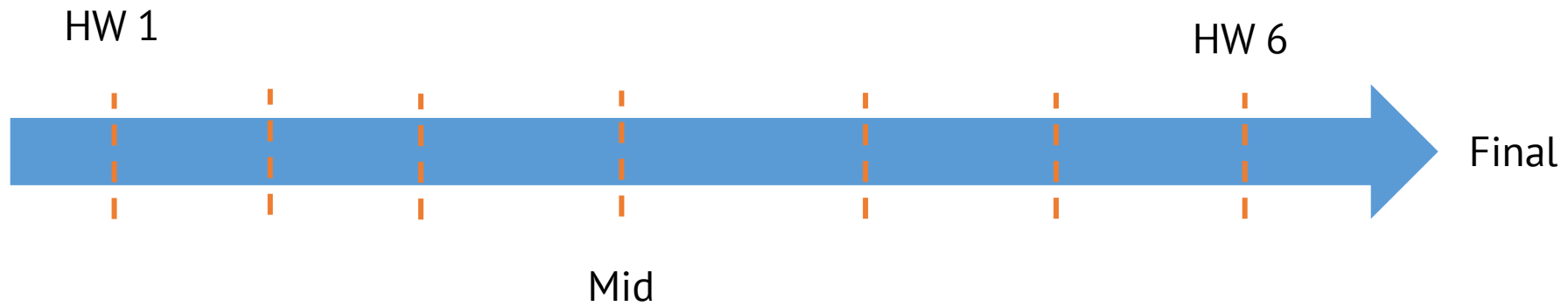
# Course structure

- Lectures and discussions are sufficient for homework and final exam
- Emphasis on *practical learning*
- Homework to review major concepts

<b>Homework</b>	<b>30% (6)</b>
<b>Mid</b>	<b>30% (October 17, Thursday )</b>
<b>Final</b>	<b>40% (December 12, 2-4pm, cumulative)</b>

# Approximate schedule

- Course homepage: <https://brightspace.usc.edu/d2l/home/114204>
- 6 homework assignments
- Final in finals week
- Mid October 17 in class



# Course content

ECE 105: WEEKLY COURSE SCHEDULE

Week	Day	Dates	Topic	Deliverables
Week 1	Tuesday	8/27	Introduction to EE, ECE 105	
	Thursday	8/29	Electronic system design	
Week 2	Tuesday	9/3	Electronic system design	
	Thursday	9/5	Circuit analysis	
Week 3	Tuesday	9/10	Circuit analysis	HW1 on circuits released
	Thursday	9/12	Devices: semiconductors	
Week 4	Tuesday	9/17	Devices: semiconductors	HW1 on circuits due
	Thursday	9/19	Devices: optoelectronics	
Week 5	Tuesday	9/24	Devices: optoelectronics	HW2 on devices released
	Thursday	9/26	Sensors	
Week 6	Tuesday	10/1	Biosensing system	HW2 on devices due
	Thursday	10/3	Biosensing system	
Week 7	Tuesday	10/8	Biosensing system	
	Thursday	10/10	Fall break	
Week 8	Tuesday	10/15	Biosensing system	HW3 on system released
	Thursday	10/17	Midterm	
Week 9	Tuesday	10/22	Introduction to AI/ML	HW3 on system due
	Thursday	10/24	Linear algebra	
Week 10	Tuesday	10/29	No Class	
	Thursday	10/31	Linear algebra	HW4 on linear algebra released
Week 11	Tuesday	11/5	Neural networks	
	Thursday	11/7	Neural networks	HW4 on linear algebra due
Week 12	Tuesday	11/12	Neural networks	HW5 on neural network released
	Thursday	11/14	Imager	
Week 13	Tuesday	11/19	Introduction to communication systems	HW5 on neural network due
	Thursday	11/21	Optical communications	
Week 14	Tuesday	11/26	Optical communications	HW6 on optical comm released
	Thursday	11/28	Thanksgiving	
Week 15	Tuesday	12/3	Optical communications	HW6 on optical comm due
	Thursday	12/5	Quantum computing	
	Tuesday	12/12	Final (2pm – 4pm)	

- 6 homeworks are on 6 modules
  - Circuits
  - Devices
  - Systems
  - Linear algebra
  - Neural network
  - Communication systems
- Midterm will cover circuits, devices, and biosensing systems
- Final will cover everything.

# Custom demonstration board for EE 105

Circuits

Voltage dividers

Arduino Nano 33  
BLE

Electronic devices  
Diodes  
Transistors

Module 2: Devices

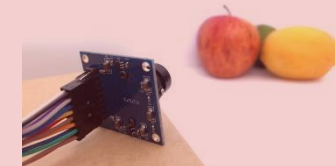
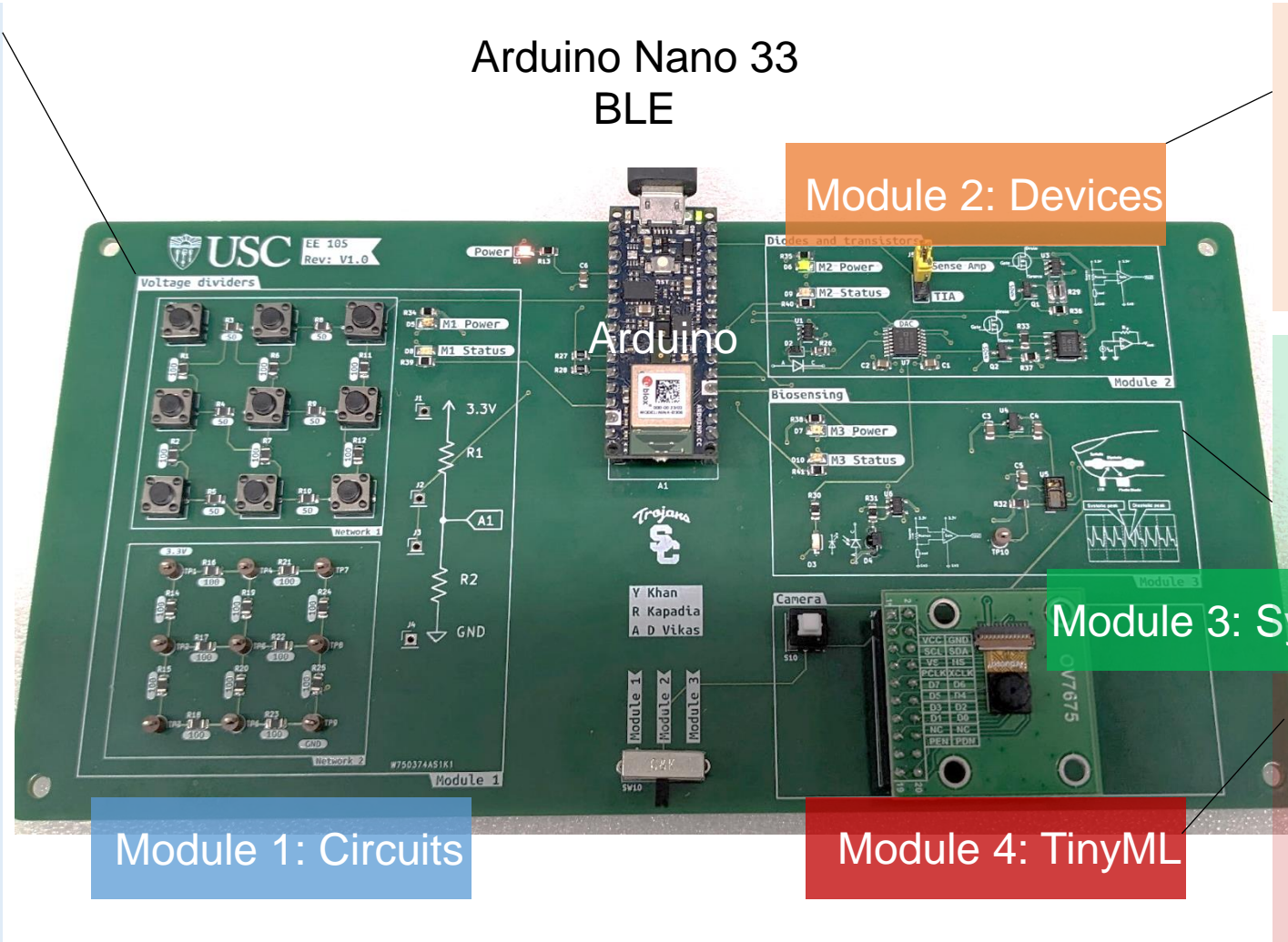
Electronic systems  
Optical  
communication  
system  
Oximeter

Module 3: Systems

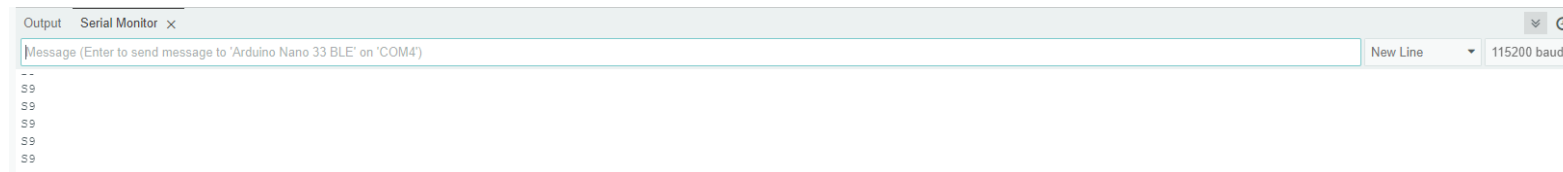
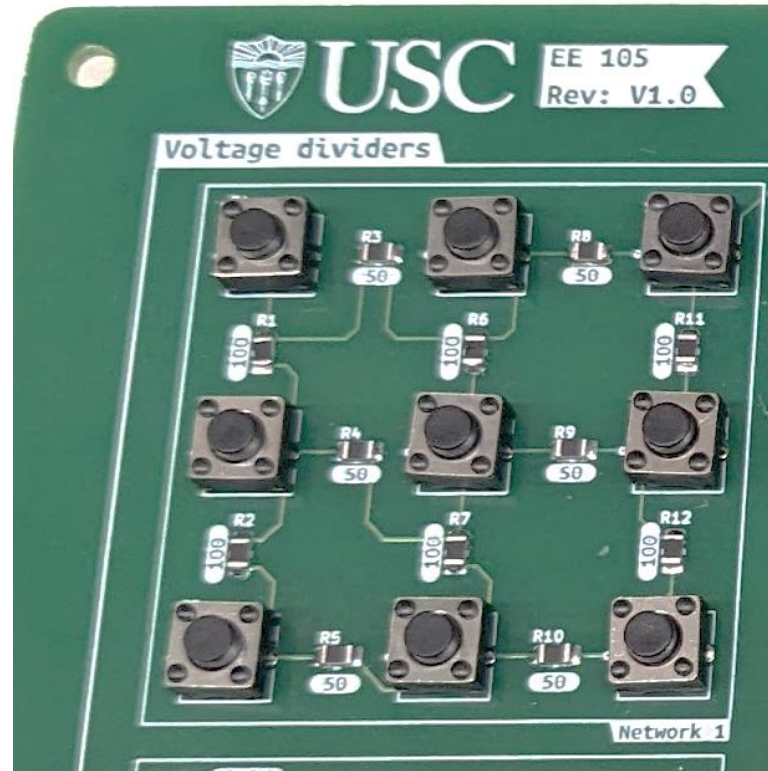
Machine vision

Module 1: Circuits

Module 4: TinyML

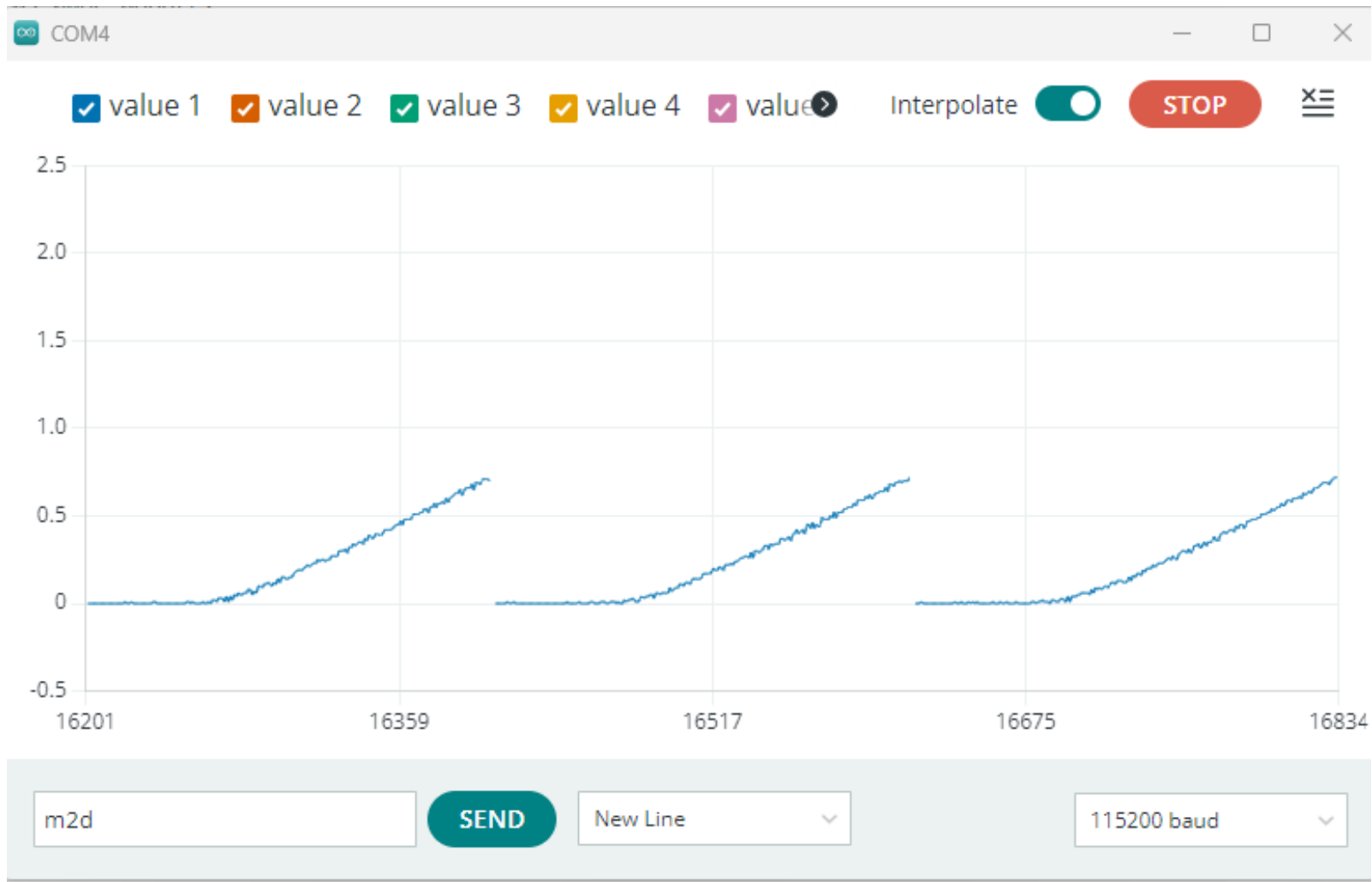


# Module 1 on circuits – demo resistive touchscreen



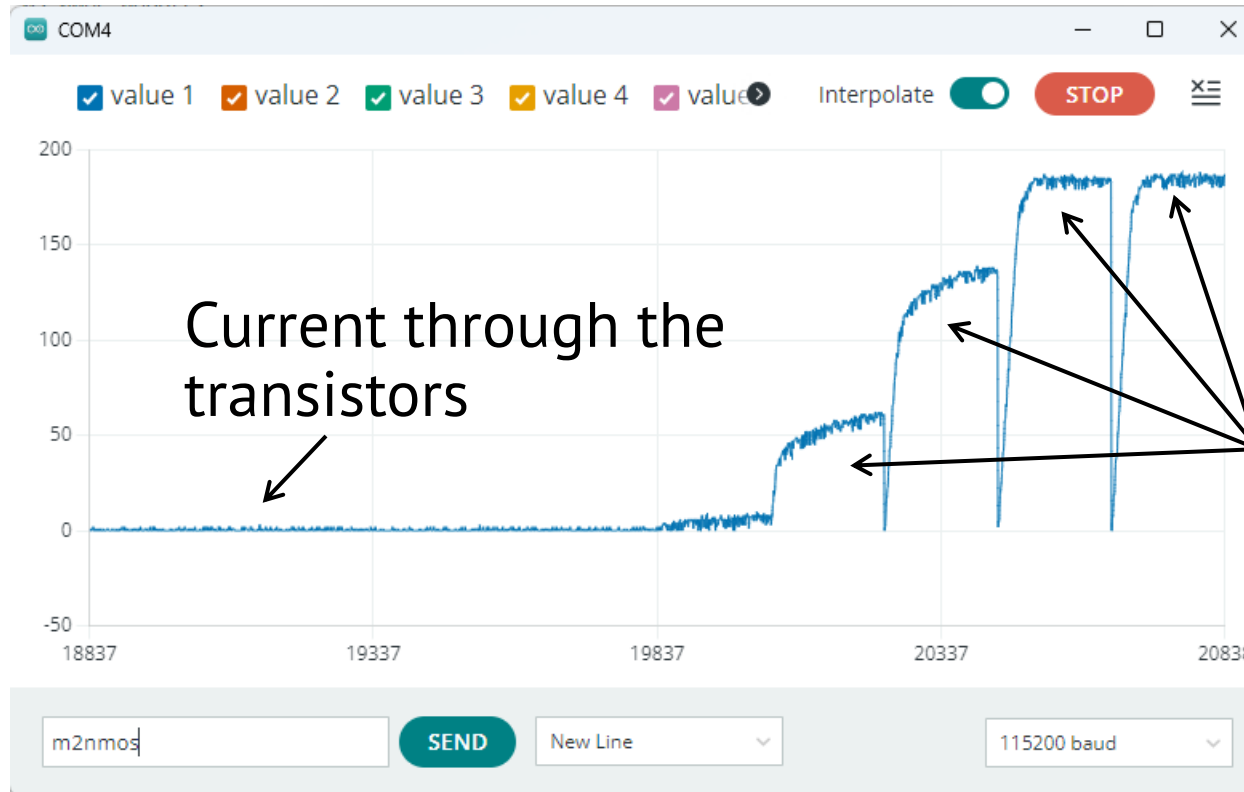
Finds the pressed button location automatically

# Module 2: diodes and transistors



Characterize  
semiconductor  
diode – how do they  
work

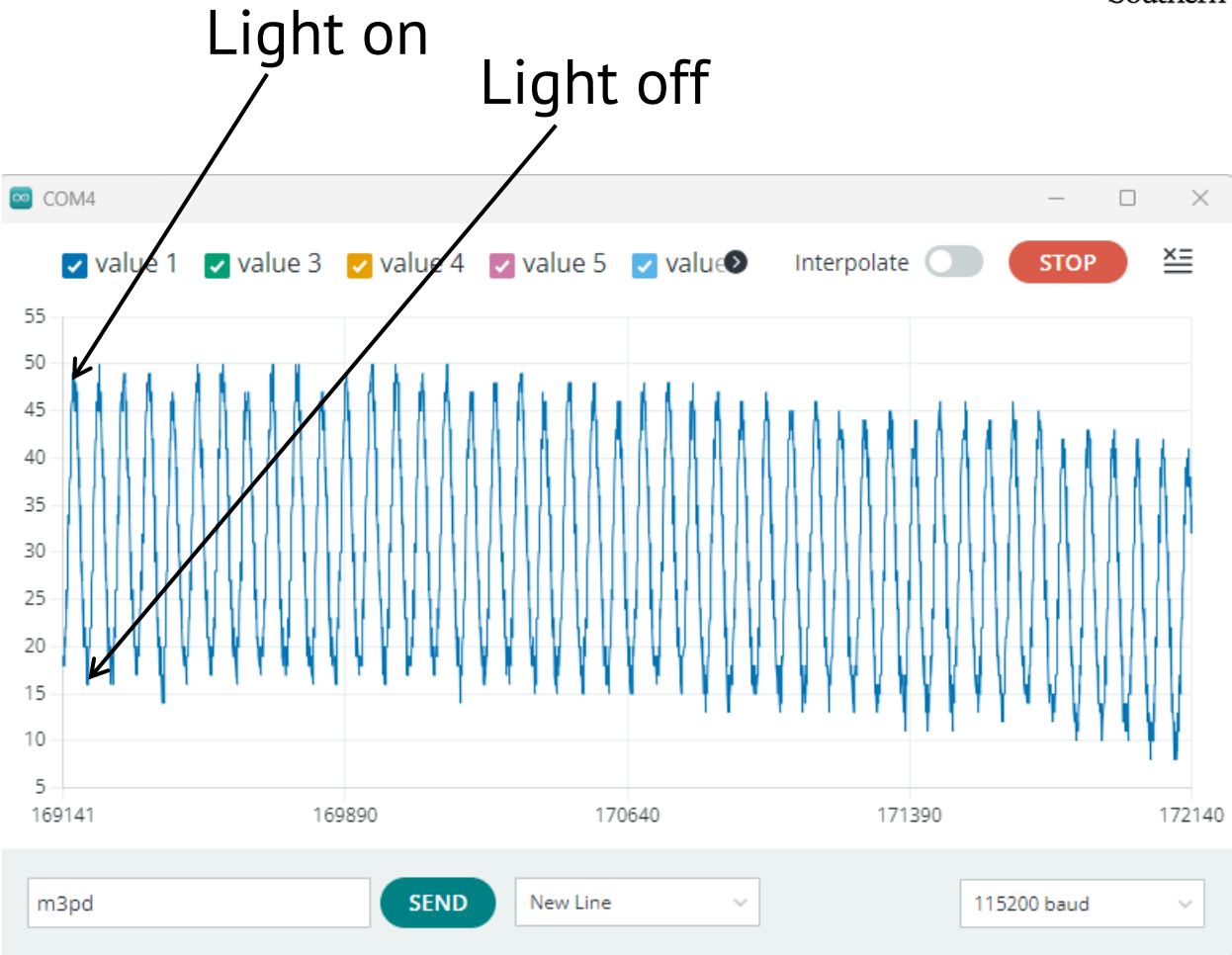
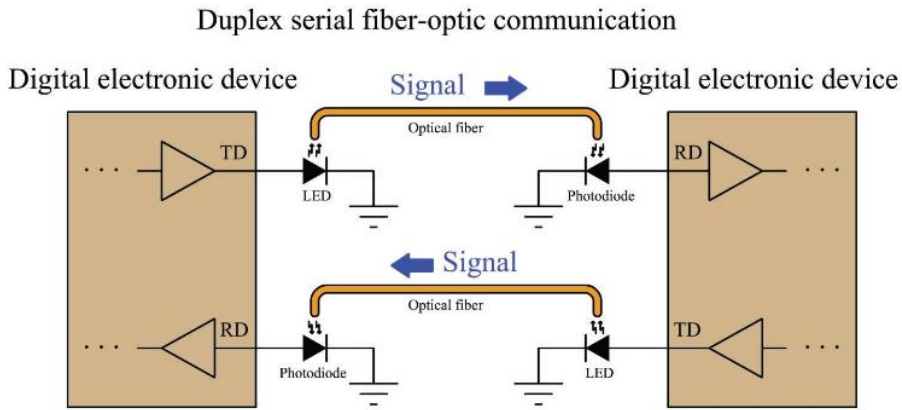
# Module 2: diodes and transistors



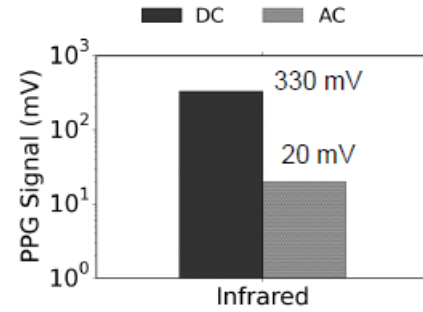
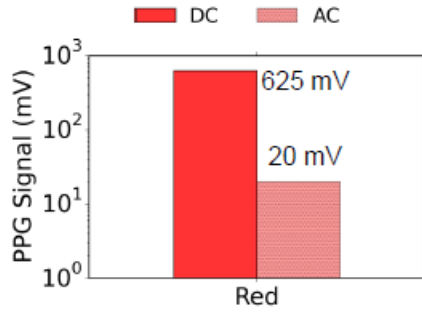
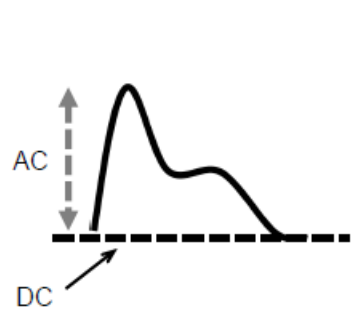
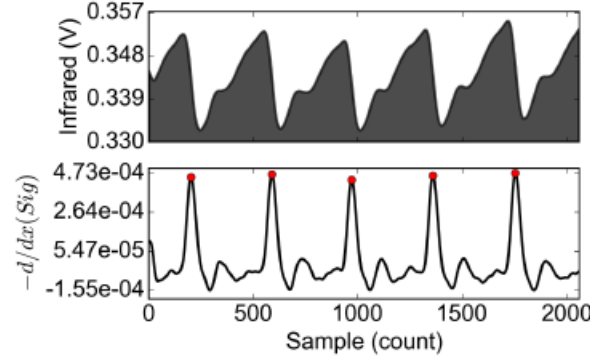
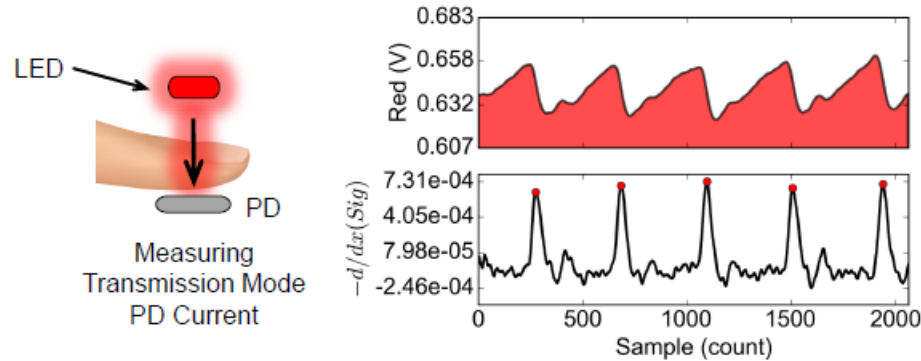
Characterize semiconductor transistors – how do they work

Increasing gate voltage / opening faucet in the water analogy

# Module 3: optical communication



# Module 3: oximeter

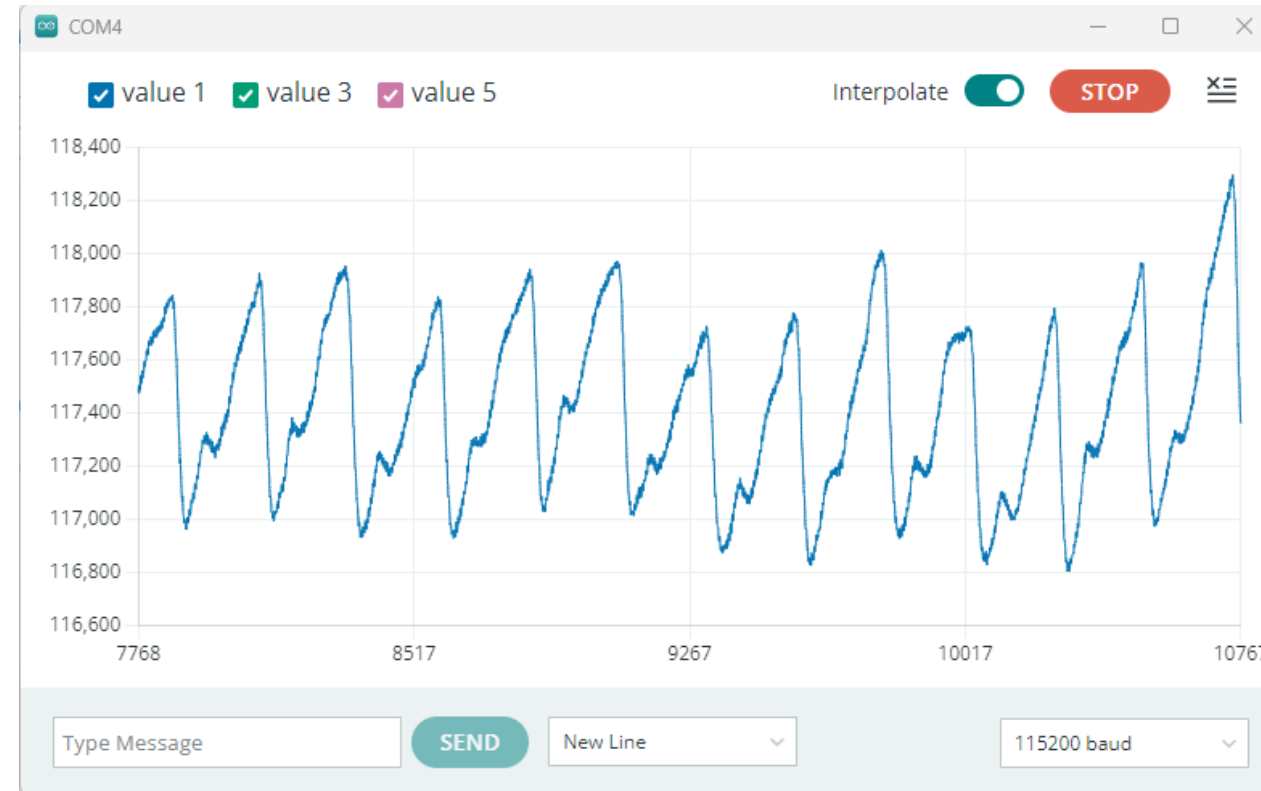


$$R = \frac{AC_{rd}/DC_{rd}}{AC_{ir}/DC_{ir}}$$

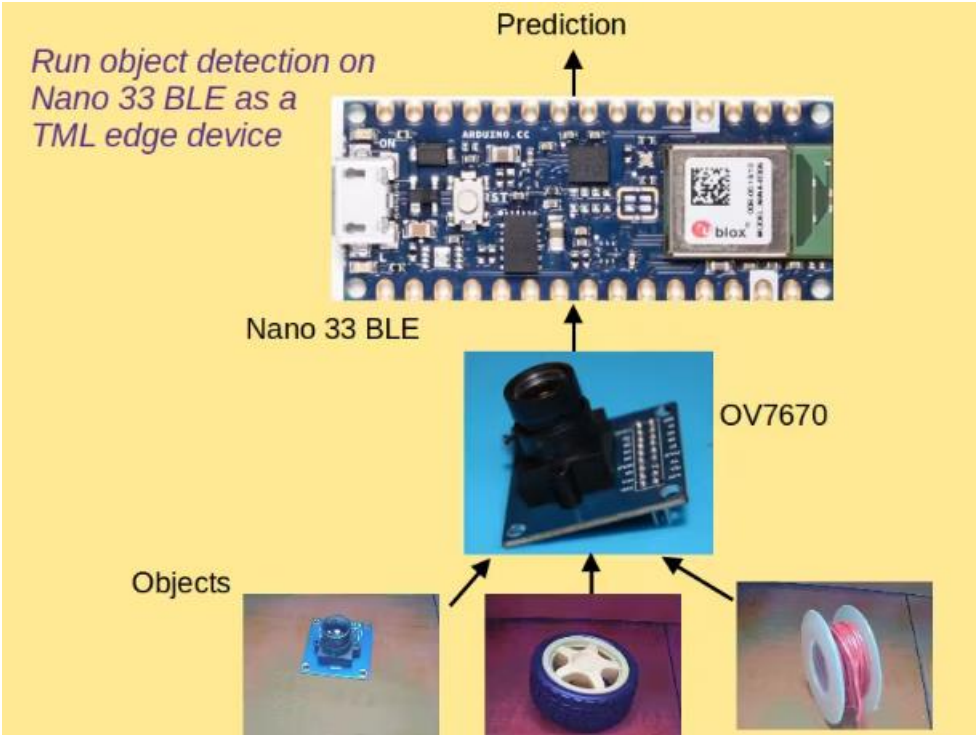
$$R = \frac{20\text{mV}/625\text{mV}}{20\text{mV}/330\text{mV}} = .528$$

$$SpO_2 = 110 - 25 * R = 97\%$$

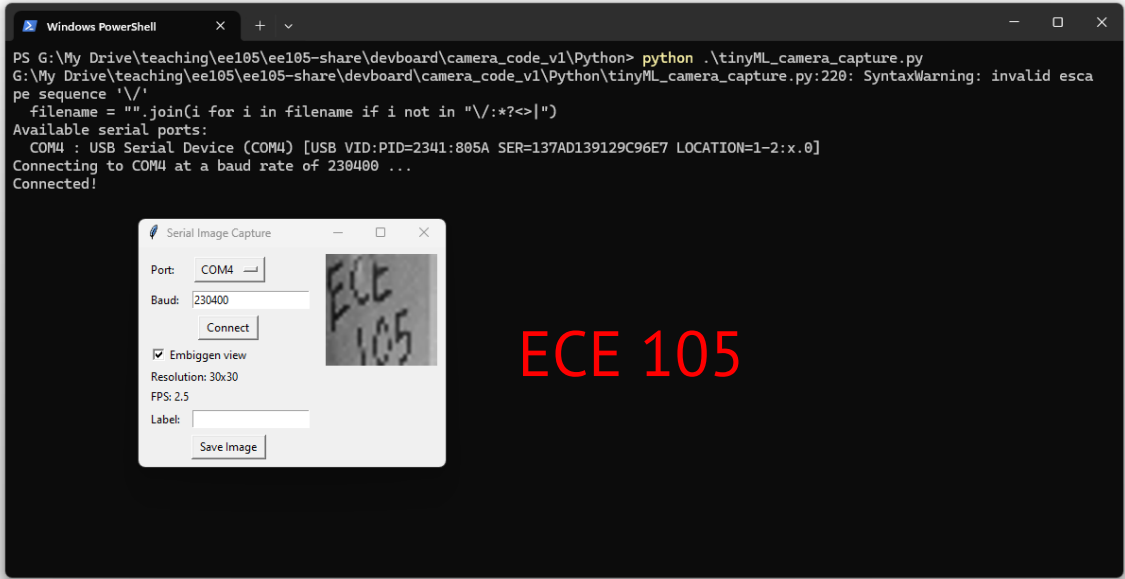
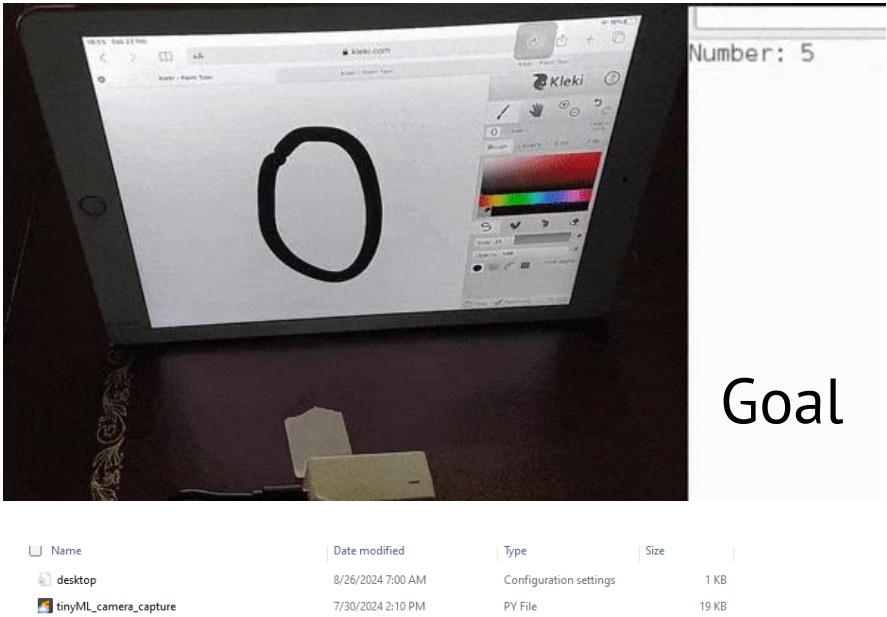
# Module 3: oximeter



# Module 4: Machine vision



Arduino + camera + ML =  
identify objects / letters /  
faces / anything



ECE 105

# Next lecture: system design

